TCA9535 具有中断输出和配置寄存器的低电压 16 位 I²C 和 SMBus 低功耗 I/O 扩展器

1 特性

- I²C 至并行端口扩展器
- 1.65V 至 5V 的宽电源电压范围
- 低待机电流消耗
- 开漏电路低电平有效中断输出
- 可耐受 5V 电压的 I/O 端口
- 400kHz 快速 I²C 总线
- 极性反转寄存器
- 针对多达 8 个器件使用的 3 个硬件地址引脚寻址
- 具有高电流驱动能力的锁存输出，用于直接驱动 LED
- 闩锁性能超过 100mA，符合 JESD 78 II 类规范
- ESD 保护性能超过 JESD 22 规范要求
  - 2000V 人体模型 (A114-A)
  - 1000V 带电器件模型 (C101)

2 应用

- 服务器
- 路由器（电信交换设备）
- 个人计算机
- 个人电子产品（例如，游戏机）
- 工业自动化
- 采用 GPIO 受限处理器的产品

3 说明

TCA9535 是一款 24 引脚器件，可为两线双向 I²C 总线或 (SMBus) 协议提供 16 位通用并行输入和输出 (I/O) 扩展。该器件可在 1.65V 至 5.5V 的电源电压范围内工作。

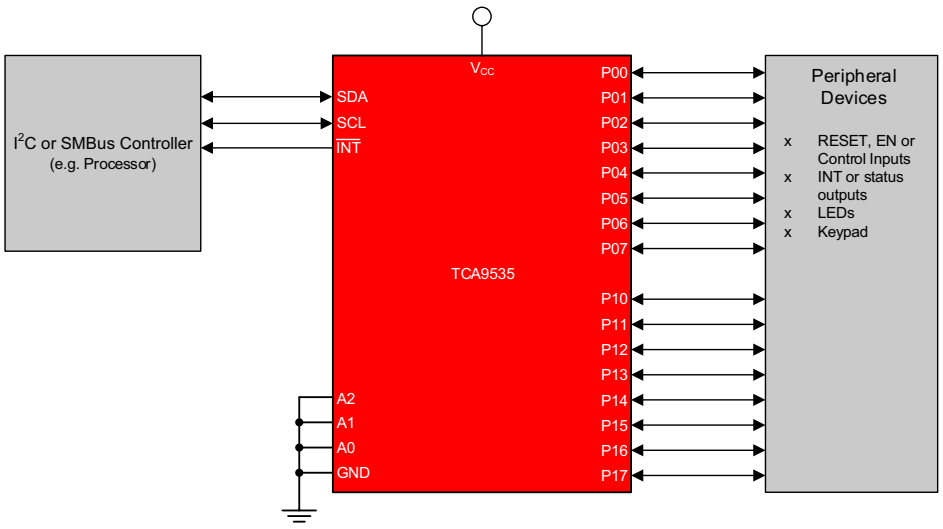
TCA9535 由两个 8 位配置（输入或输出可选）、输入端口、输出端口和极性反转（高电平有效或低电平有效运行）寄存器组成。在加电时，I/O 被配置为输入。系统控制器可通过写入 I/O 配置位将 I/O 启用为输入或输出。

TCA9535 除了不包含内部 I/O 上拉电阻器（配置为输入和非驱动时，需要上拉和下拉未用的 I/O 引脚），与 TCA9555 完全相同。

器件信息

器件型号	封装(1)	封装尺寸（标称值）
TCA9535	TSSOP (24)	7.80mm x 4.40mm
	SSOP (24)	6.20mm x 5.30mm
	WQFN (24)	4.00mm x 4.00mm
	VQFN (24)	4.00mm x 4.00mm

(1) 如需了解所有可用封装，请参阅产品说明书末尾的可订购产品附录。



方框图

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4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision D (June 2016) to Revision E (May 2022) — **Page**

- 将提到 I^2C 的旧术语实例通篇更改为控制器和目标.....1
- Changed V_{CC} to GND on the Controlled Switch in 图 8-1 24

Changes from Revision C (May 2016) to Revision D (June 2016) — **Page**

- 添加了 DB 封装.....1

Changes from Revision B (August 2015) to Revision C (May 2016) — **Page**

- 添加了 RGE 封装.....1
- Added I_{OL} for different T_j 5
- Deleted ΔI_{CC} spec from the Electrical Characteristics table, added ΔI_{CC} typical characteristics graph.....6
- Changed I_{CC} standby into different input states, with increased maximums 6
- Changed C_{io} maximum 6

Changes from Revision A (September 2009) to Revision B (August 2015) — **Page**

- 添加了 *引脚配置和功能* 部分、*ESD 等级* 表、*特性说明* 部分、*器件功能模式*、*应用和实施* 部分、*电源相关建议* 部分、*布局* 部分、*器件和文档支持* 部分以及 *机械、封装和可订购信息* 部分.....1

5 Pin Configuration and Functions

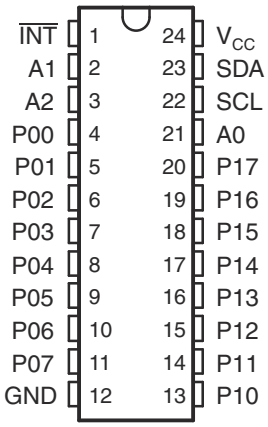
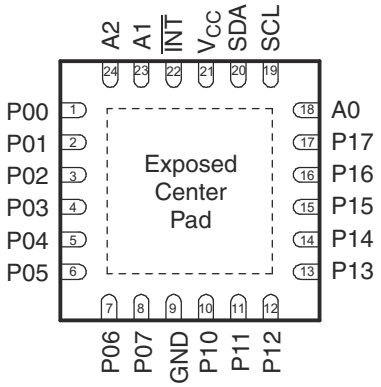


图 5-1. DB, PW (TSSOP) Package 24-Pin (Top View)



The exposed center pad, if used, must be connected as a secondary ground or left electrically open.

图 5-2. RTW (WQFN), RGE (VQFN) Package 24-Pin (Top View)

表 5-1. Pin Functions

PIN			TYPE	DESCRIPTION
NAME	NO.			
	DB, PW	RTW, RGE		
A0	21	18	Input	Address input 0. Connect directly to V_{CC} or ground
A1	2	23	Input	Address input 1. Connect directly to V_{CC} or ground
A2	3	24	Input	Address input 2. Connect directly to V_{CC} or ground
GND	12	9	—	Ground
$\overline{INT}$	1	22	Output	Interrupt output. Connect to V_{CC} through an external pull-up resistor
P00(1)	4	1	I/O	P-port I/O. Push-pull design structure. At power on, P00 is configured as an input
P01(1)	5	2	I/O	P-port I/O. Push-pull design structure. At power on, P01 is configured as an input
P02(1)	6	3	I/O	P-port I/O. Push-pull design structure. At power on, P02 is configured as an input
P03(1)	7	4	I/O	P-port I/O. Push-pull design structure. At power on, P03 is configured as an input
P04(1)	8	5	I/O	P-port I/O. Push-pull design structure. At power on, P04 is configured as an input
P05(1)	9	6	I/O	P-port I/O. Push-pull design structure. At power on, P05 is configured as an input
P06(1)	10	7	I/O	P-port I/O. Push-pull design structure. At power on, P06 is configured as an input
P07(1)	11	8	I/O	P-port I/O. Push-pull design structure. At power on, P07 is configured as an input
P10(1)	13	10	I/O	P-port I/O. Push-pull design structure. At power on, P10 is configured as an input
P11(1)	14	11	I/O	P-port I/O. Push-pull design structure. At power on, P11 is configured as an input
P12(1)	15	12	I/O	P-port I/O. Push-pull design structure. At power on, P12 is configured as an input
P13(1)	16	13	I/O	P-port I/O. Push-pull design structure. At power on, P13 is configured as an input
P14(1)	17	14	I/O	P-port I/O. Push-pull design structure. At power on, P14 is configured as an input
P15(1)	18	15	I/O	P-port I/O. Push-pull design structure. At power on, P15 is configured as an input
P16(1)	19	16	I/O	P-port I/O. Push-pull design structure. At power on, P16 is configured as an input
P17(1)	20	17	I/O	P-port I/O. Push-pull design structure. At power on, P17 is configured as an input
SCL	22	19	Input	Serial clock bus. Connect to V_{CC} through a pull-up resistor
SDA	23	20	Input	Serial data bus. Connect to V_{CC} through a pull-up resistor

表 5-1. Pin Functions (continued)

PIN			TYPE	DESCRIPTION
NAME	NO.			
	DB, PW	RTW, RGE		
V_{CC}	24	21	—	Supply voltage

(1) If port is unused, it must be tied to either V_{CC} or GND through a resistor of moderate value (about 10 kΩ)

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		– 0.5	6	V
V_I	Input voltage(2)		– 0.5	6	V
V_O	Output voltage(2)		– 0.5	6	V
I_{IK}	Input clamp current	V_I < 0		– 20	mA
I_{OK}	Output clamp current	V_O < 0		– 20	mA
I_{IOK}	Input-output clamp current	V_O < 0 or V_O > V_{CC}		±20	mA
I_{OL}	Continuous output low current	V_O = 0 to V_{CC}		50	mA
I_{OH}	Continuous output high current	V_O = 0 to V_{CC}		– 50	mA
I_{CC}	Continuous current through GND			– 250	mA
	Continuous current through V_{CC}			160	mA
$T_{j(MAX)}$	Maximum junction temperature			100	°C
T_{stg}	Storage temperature		– 65	150	°C

(1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. Absolute maximum ratings do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If briefly operating outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not sustain damage, but it may not be fully functional. Operating the device in this manner may affect device reliability, functionality, performance, and shorten the device lifetime.
(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

				MIN	MAX	UNIT
V_{CC}	Supply voltage			1.65	5.5	V
V_{IH}	High-level input voltage	SCL, SDA		0.7 × V_{CC}	V_{CC} (1)	V
		A2 – A0, P07 – P00, P17 – P10		0.7 × V_{CC}	5.5	V
V_{IL}	Low-level input voltage	SCL, SDA, A2 – A0, P07 – P00, P17 – P10		– 0.5	0.3 × V_{CC}	V
I_{OH}	High-level output current	P07 – P00, P17 – P10			– 10	mA
I_{OL}	Low-level output current(2)	P07 – P00, P17 – P10	$T_j \leqslant 65°C$		25	mA
			$T_j \leqslant 85°C$		18	
			$T_j \leqslant 100°C$		11	
I_{OL}	Low-level output current(2)	$\overline{INT}$, SDA	$T_j \leqslant 85°C$		6	mA
			$T_j \leqslant 100°C$		3.5	
T_A	Operating free-air temperature			– 40	85	°C

(1) For voltages applied above V_{CC}, an increase in I_{CC} results.
(2) The values shown apply to specific junction temperatures, which depend on the $R_{\theta JA}$ of the package used. See the *Calculating Junction Temperature and Power Dissipation* section on how to calculate the junction temperature.

6.4 Thermal Information

THERMAL METRIC[1]		TCA9535				UNIT
		PW (TSSOP)	DB (SSOP)	RTW (WQFN)	RGE (VQFN)	
		24 PINS	24 PINS	24 PINS	24 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	108.8	92.9	43.6	48.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	54	53.5	46.2	58.1	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	62.8	50.4	22.1	27.1	°C/W
ψ_{JT}	Junction-to-top characterization parameter	11.1	21.9	1.5	3.3	°C/W
ψ_{JB}	Junction-to-board characterization parameter	62.3	50.1	22.2	27.2	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	10.7	15.3	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS	V_{CC}	MIN	TYP[1]	MAX	UNIT
V_{IK}	Input diode clamp voltage		I_I = –18 mA	1.65 V to 5.5 V	–1.2			V
V_{PORR}	Power-on reset voltage, V_{CC} rising		V_I = V_{CC} or GND, I_O = 0			1.2	1.5	V
V_{PORF}	Power-on reset voltage, V_{CC} falling		V_I = V_{CC} or GND, I_O = 0		0.75	1		V
V_{OH}	P-port high-level output voltage[2]		I_{OH} = –8 mA	1.65 V	1.2			V
				2.3 V	1.8			
				3 V	2.6			
				4.75 V	4.1			
			I_{OH} = –10 mA	1.65 V	1			
				2.3 V	1.7			
				3 V	2.5			
				4.75 V	4			
I_{OL}	Low-level output current	SDA	V_{OL} = 0.4 V	1.65 V to 5.5 V	3			mA
		P port[3]	V_{OL} = 0.5 V	1.65 V to 5.5 V	8			
			V_{OL} = 0.7 V	1.65 V to 5.5 V	10			
		$\overline{INT}$	V_{OL} = 0.4 V	1.65 V to 5.5 V	3			
I_I	Input leakage current	SCL, SDA Input leakage	V_I = V_{CC} or GND	1.65 V to 5.5 V			±1	µA
		A2 – A0 Input leakage	V_I = V_{CC} or GND	1.65 V to 5.5 V			±1	
I_{IH}	Input high leakage current	P port	V_I = V_{CC}	1.65 V to 5.5 V			1	µA
I_{IL}	Input low leakage current	P port	V_I = GND	1.65 V to 5.5 V			–1	µA

6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS	V_{CC}	MIN	TYP(1)	MAX	UNIT
I_{CC}	Quiescent current	Operating mode	V_I = V_{CC} or GND, I_O = 0, I/O = inputs, f_{SCL} = 400 kHz, No load	5.5 V		22	40	μA
				3.6 V		11	30	
				2.7 V		8	19	
				1.95 V		5	11	
		Standby mode	V_I = V_{CC}, I_O = 0, I/O = inputs, f_{SCL} = 0 kHz, No load	5.5 V		1.5	3.9	
				3.6 V		0.9	2.2	
				2.7 V		0.6	1.8	
				1.95 V		0.6	1.5	
			V_I = GND, I_O = 0, I/O = inputs, f_{SCL} = 0 kHz, No load	5.5 V		1.5	8.7	
				3.6 V		0.9	4	
				2.7 V		0.6	3	
				1.95 V		0.4	2.2	
C_I	Input capacitance	SCL	V_I = V_{CC} or GND	1.65 V to 5.5 V		3	8	pF
C_{io}	Input-output pin capacitance	SDA	V_{IO} = V_{CC} or GND	1.65 V to 5.5 V		3	9.5	pF
		P port	V_{IO} = V_{CC} or GND	1.65 V to 5.5 V		3.7	9.5	

(1) All typical values are at nominal supply voltage (1.8-, 2.5-, 3.3-, or 5-V V_{CC}) and T_A = 25°C.
(2) Each I/O must be externally limited to a maximum of 25 mA, and each octal (P07 – P00 and P17 – P10) must be limited to a maximum current of 100 mA, for a device total of 200 mA.
(3) The total current sourced by all I/Os must be limited to 160 mA (80 mA for P07 – P00 and 80 mA for P17 – P10).

6.6 I²C Interface Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see 图 7-2)

			MIN	MAX	UNIT
I²C BUS—STANDARD MODE					
f_{scl}	I²C clock frequency		0	100	kHz
t_{sch}	I²C clock high time		4		μs
t_{scl}	I²C clock low time		4.7		μs
t_{sp}	I²C spike time			50	ns
t_{sds}	I²C serial-data setup time		250		ns
t_{sdh}	I²C serial-data hold time		0		ns
t_{icr}	I²C input rise time			1000	ns
t_{icf}	I²C input fall time			300	ns
t_{ocf}	I²C output fall time	10-pF to 400-pF bus		300	ns
t_{buf}	I²C bus free time between stop and start		4.7		μs
t_{sts}	I²C start or repeated start condition setup		4.7		μs
t_{sth}	I²C start or repeated start condition hold		4		μs
t_{sps}	I²C stop condition setup		4		μs
$t_{vd(data)}$	Valid data time	SCL low to SDA output valid		3.45	μs
$t_{vd(ack)}$	Valid data time of ACK condition	ACK signal from SCL low to SDA (out) low		3.45	μs
C_b	I²C bus capacitive load			400	pF
I²C BUS—FAST MODE					
f_{scl}	I²C clock frequency		0	400	kHz
t_{sch}	I²C clock high time		0.6		μs
t_{scl}	I²C clock low time		1.3		μs

6.6 I²C Interface Timing Requirements (continued)

over recommended operating free-air temperature range (unless otherwise noted) (see 图 7-2)

			MIN	MAX	UNIT
t_{sp}	I²C spike time			50	ns
t_{sds}	I²C serial-data setup time		100		ns
t_{sdh}	I²C serial-data hold time		0		ns
t_{icr}	I²C input rise time		20	300	ns
t_{icf}	I²C input fall time		20 × (V_{CC} / 5.5 V)	300	ns
t_{ocf}	I²C output fall time	10-pF to 400-pF bus	20 × (V_{CC} / 5.5 V)	300	ns
t_{buf}	I²C bus free time between stop and start		1.3		µs
t_{sts}	I²C start or repeated start condition setup		0.6		µs
t_{sth}	I²C start or repeated start condition hold		0.6		µs
t_{sps}	I²C stop condition setup		0.6		µs
$t_{vd(data)}$	Valid data time	SCL low to SDA output valid		0.9	µs
$t_{vd(ack)}$	Valid data time of ACK condition	ACK signal from SCL low to SDA (out) low		0.9	µs
C_b	I²C bus capacitive load			400	pF

6.7 Switching Characteristics

over recommended operating free-air temperature range, $C_L \leq 100$ pF (unless otherwise noted) (see 图 7-2 and 图 7-3)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
t_{iv}	Interrupt valid time	P port	$\overline{INT}$		4	µs
t_{ir}	Interrupt reset delay time	SCL	$\overline{INT}$		4	µs
t_{pv}	Output data valid; For V_{CC} = 2.3 V – 5.5 V	SCL	P port		200	ns
	Output data valid; For V_{CC} = 1.65 V – 2.3 V				300	ns
t_{ps}	Input data setup time	P port	SCL	150		ns
t_{ph}	Input data hold time	P port	SCL	1		µs

6.8 Typical Characteristics

T_A = 25°C (unless otherwise noted)

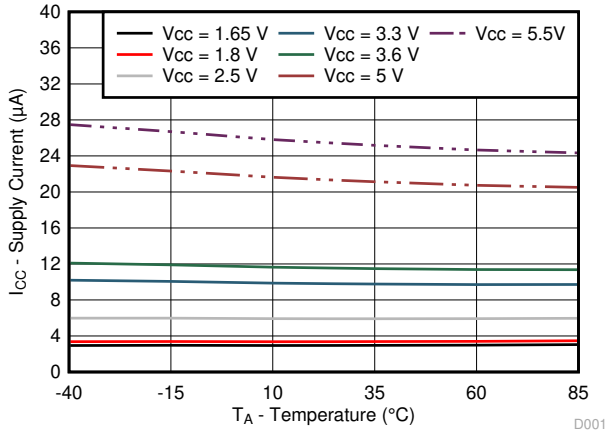


图 6-1. Supply Current vs Temperature for Different Supply Voltage (V_{CC})

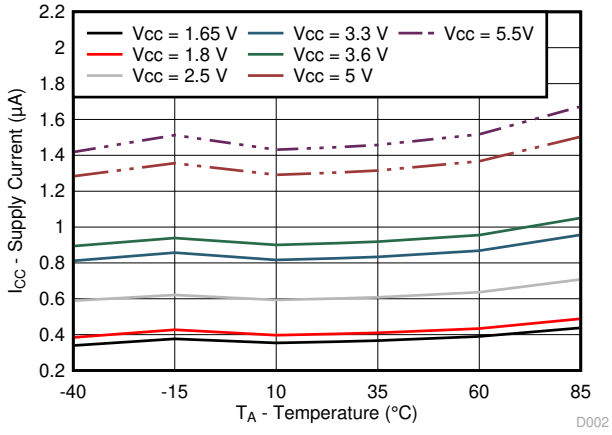


图 6-2. Standby Supply Current vs Temperature for Different Supply Voltage (V_{CC})

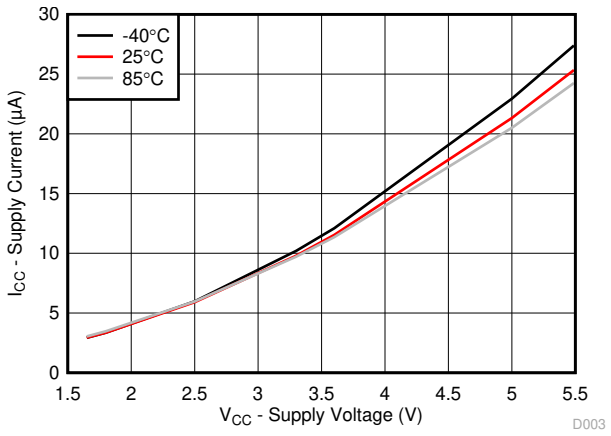


图 6-3. Supply Current vs Supply Voltage for Different Temperature (T_A)

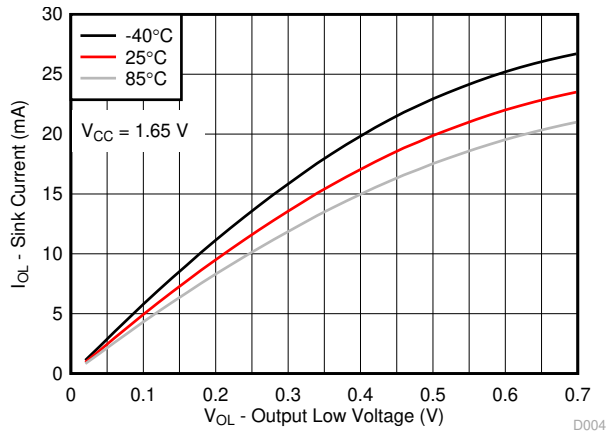


图 6-4. I/O Sink Current vs Output Low Voltage for Different Temperature (T_A) for V_{CC} = 1.65 V

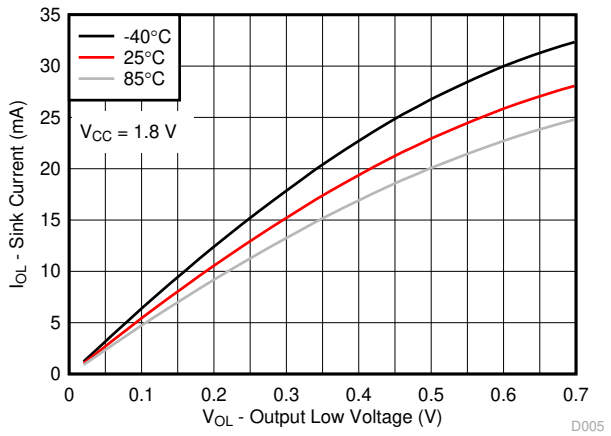


图 6-5. I/O Sink Current vs Output Low Voltage for Different Temperature (T_A) for V_{CC} = 1.8 V

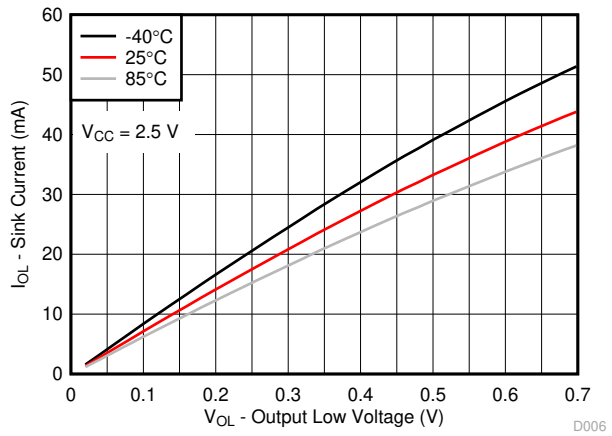


图 6-6. I/O Sink Current vs Output Low Voltage for Different Temperature (T_A) for V_{CC} = 2.5 V

6.8 Typical Characteristics (continued)

T_A = 25°C (unless otherwise noted)

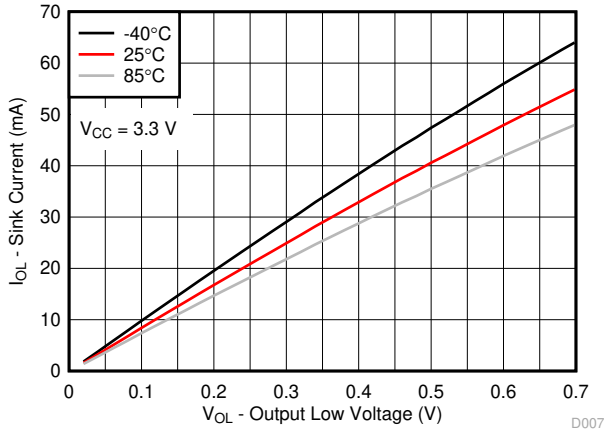


图 6-7. I/O Sink Current vs Output Low Voltage for Different Temperature (T_A) for V_{CC} = 3.3 V

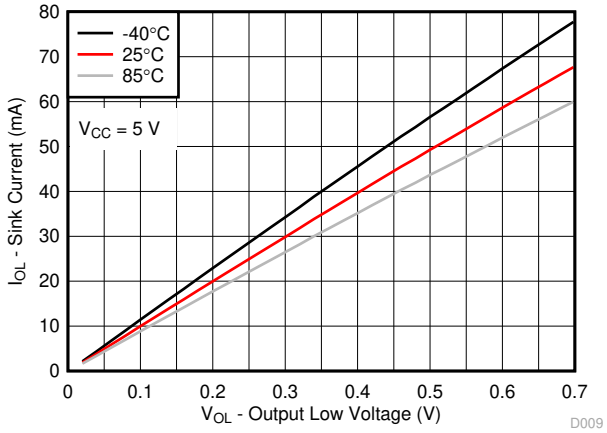


图 6-8. I/O Sink Current vs Output Low Voltage for Different Temperature (T_A) for V_{CC} = 5 V

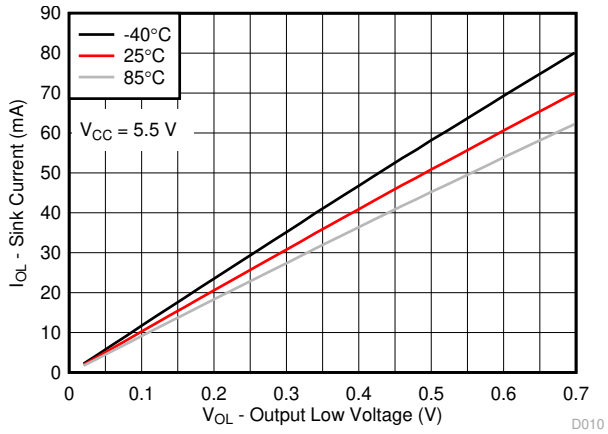


图 6-9. I/O Sink Current vs Output Low Voltage for Different Temperature (T_A) for V_{CC} = 5.5 V

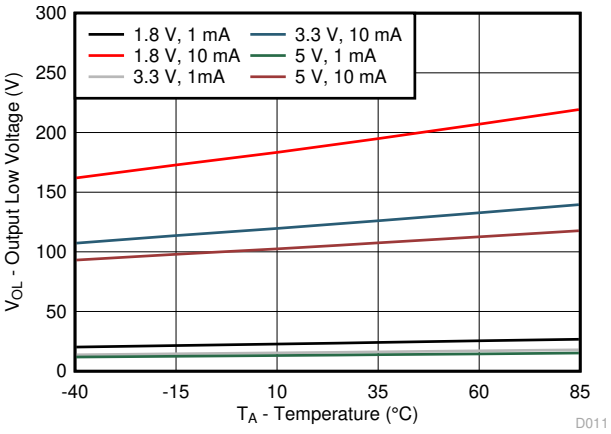


图 6-10. I/O Low Voltage vs Temperature for Different V_{CC} and I_{OL}

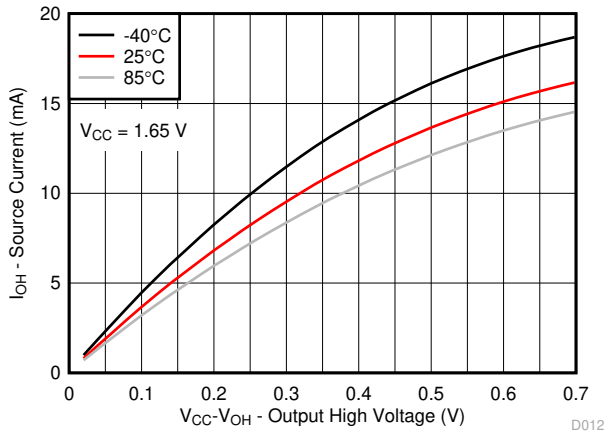


图 6-11. I/O Source Current vs Output High Voltage for Different Temperature (T_A) for V_{CC} = 1.65 V

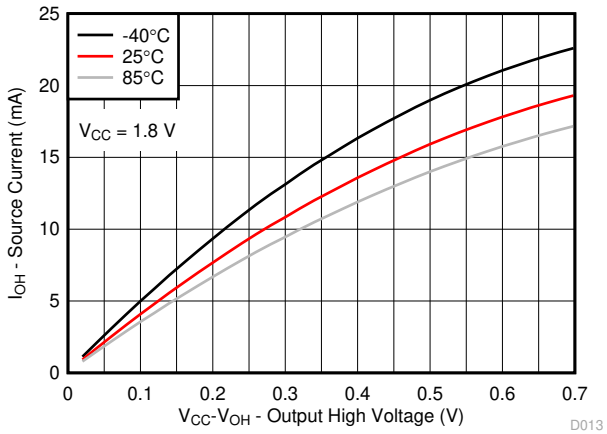


图 6-12. I/O Source Current vs Output High Voltage for Different Temperature (T_A) for V_{CC} = 1.8 V

6.8 Typical Characteristics (continued)

T_A = 25°C (unless otherwise noted)

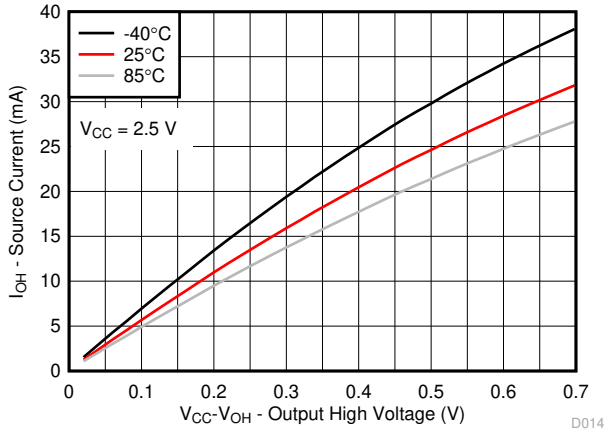


图 6-13. I/O Source Current vs Output High Voltage for Different Temperature (T_A) for V_{CC} = 2.5 V

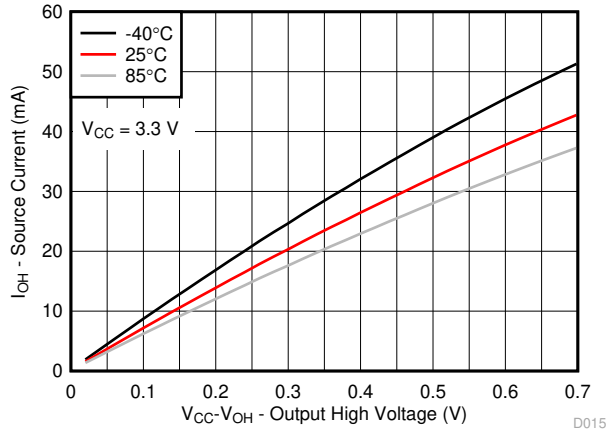


图 6-14. I/O Source Current vs Output High Voltage for Different Temperature (T_A) for V_{CC} = 3.3 V

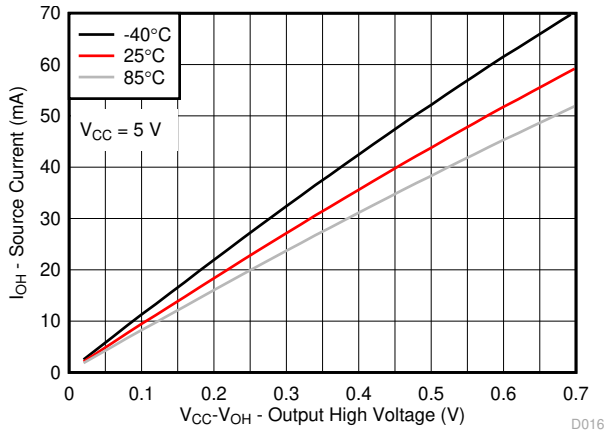


图 6-15. I/O Source Current vs Output High Voltage for Different Temperature (T_A) for V_{CC} = 5 V

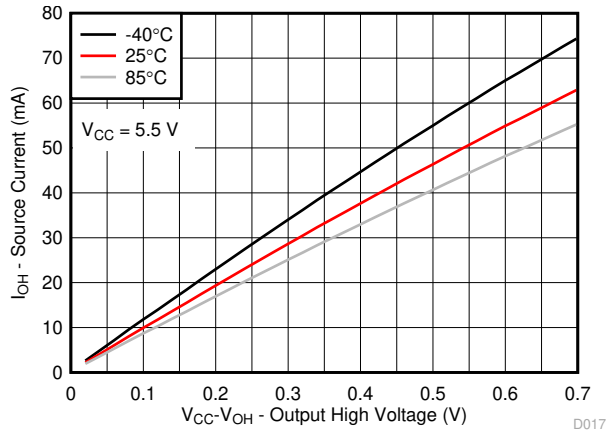


图 6-16. I/O Source Current vs Output High Voltage for Different Temperature (T_A) for V_{CC} = 5.5 V

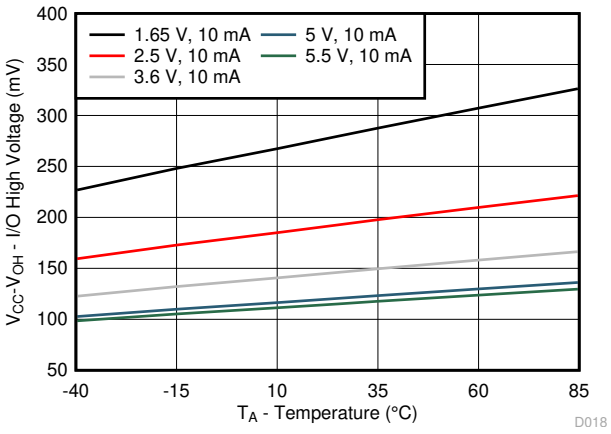


图 6-17. V_{CC} – V_{OH} Voltage vs Temperature for Different V_{CC}

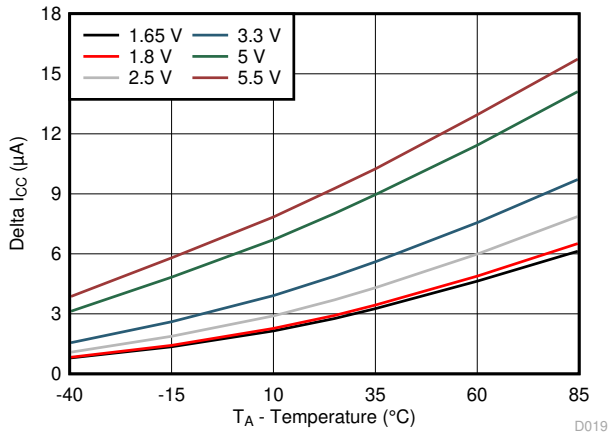
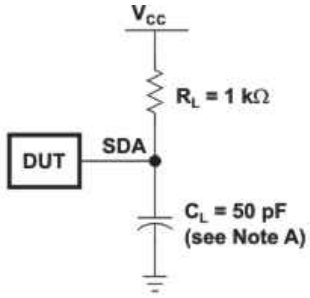
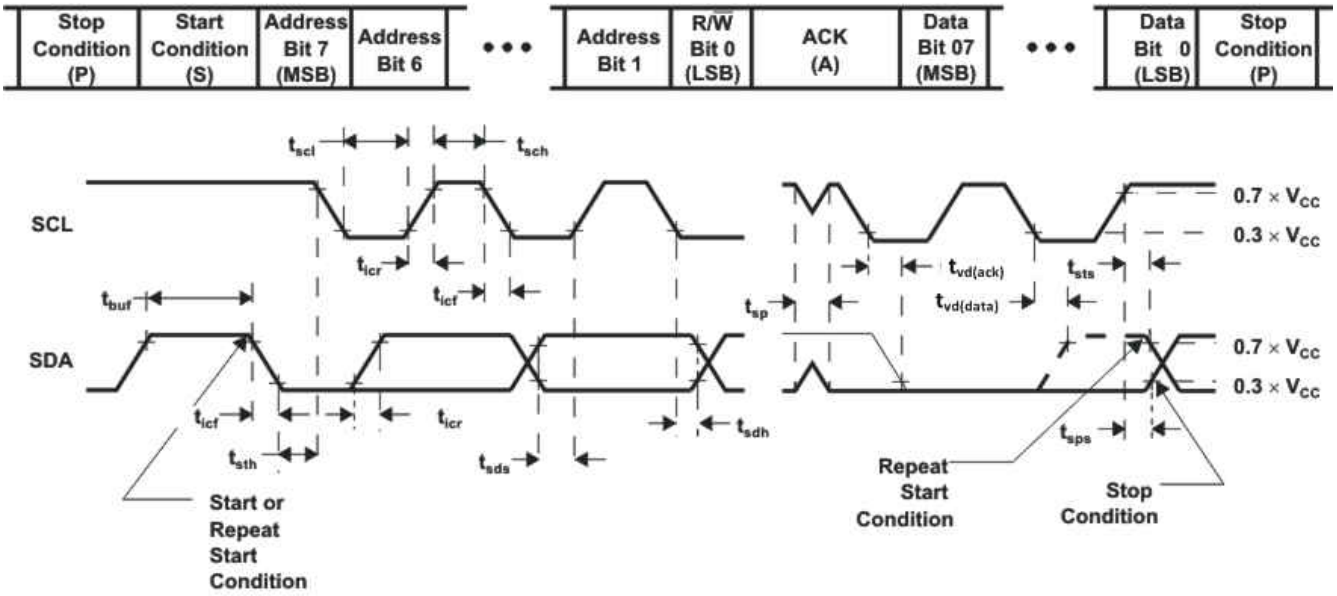


图 6-18. Δ I_{CC} vs Temperature for Different V_{CC} (V_I = V_{CC} – 0.6 V)

Parameter Measurement Information



SDA LOAD CONFIGURATION



VOLTAGE WAVEFORMS

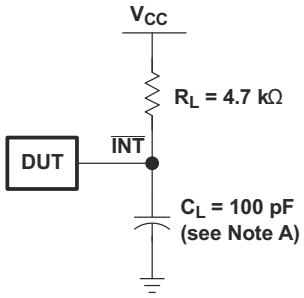
BYTE	DESCRIPTION
1	I^2C address
2, 3	P-port data

A. C_L includes probe and jig capacitance.

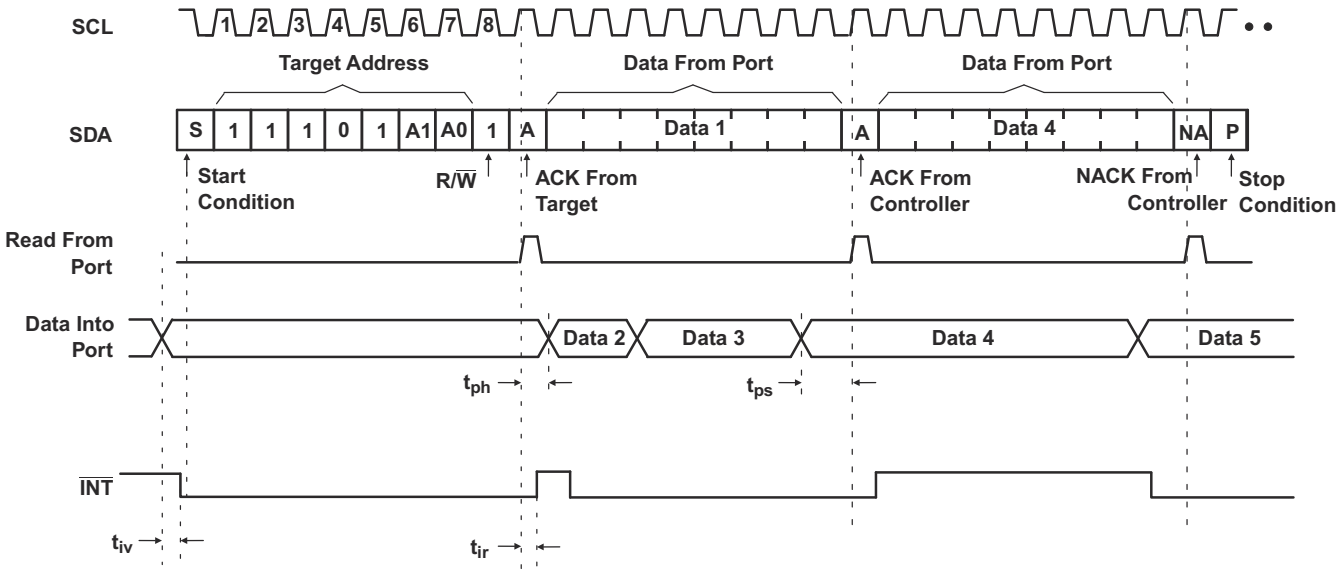
B. All inputs are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r/t_f ≤ 30 ns.

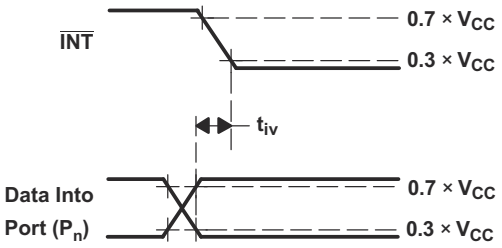
C. All parameters and waveforms are not applicable to all devices.

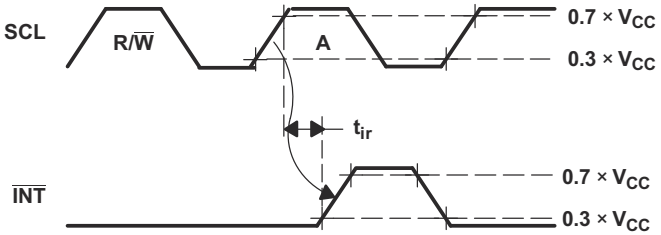
图 7-1. I^2C Interface Load Circuit and Voltage Waveforms



Interrupt Load Configuration





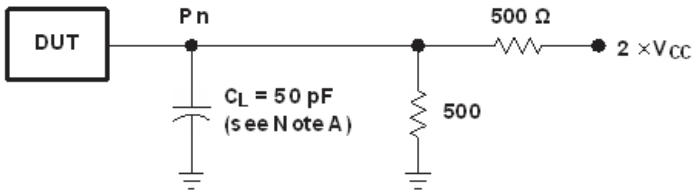


A. C_L includes probe and jig capacitance.

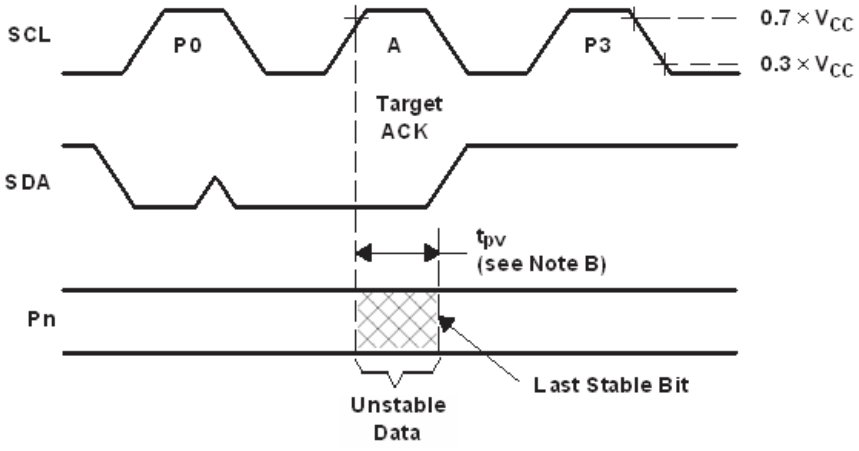
B. All inputs are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r/t_f ≤ 30 ns.

C. All parameters and waveforms are not applicable to all devices.

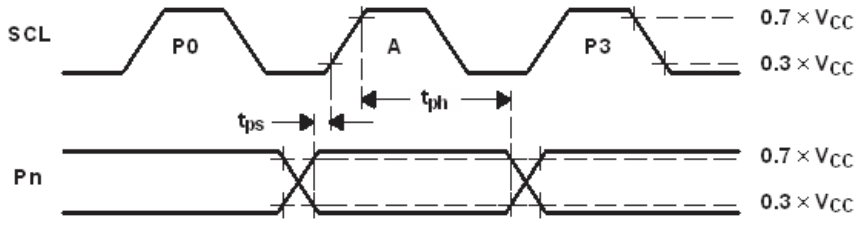
图 7-2. Interrupt Load Circuit and Voltage Waveforms



P-Port Load Configuration



Write Mode (R/W = 0)



Read Mode (R/W = 1)

A. C_L includes probe and jig capacitance.
B. t_{pv} is measured from 0.7 × V_{CC} on SCL to 50% I/O (Pn) output.
C. All inputs are supplied by generators having the following characteristics: PRR ⩽ 10 MHz, Z_O = 50 Ω, t_r/t_f ⩽ 30 ns.
D. The outputs are measured one at a time, with one transition per measurement.
E. All parameters and waveforms are not applicable to all devices.

图 7-3. P-Port Load Circuit and Voltage Waveforms

7 Detailed Description

7.1 Overview

The TCA9535 device is a 16-bit I/O expander for the I^2C bus and is designed for 1.65-V to 5.5-V V_{CC} operation. It provides general-purpose remote I/O expansion for most microcontroller families via the I^2C interface.

The TCA9535 consists of two 8-bit Configuration (input or output selection), Input Port, Output Port, and Polarity Inversion (active-high or active-low operation) registers. At power-on, the I/Os are configured as inputs. The system controller can enable the I/Os as either inputs or outputs by writing to the I/O configuration register bits. The data for each input or output is kept in the corresponding Input or output register. The polarity of the Input Port register can be inverted with the Polarity Inversion register. All registers can be read by the system controller.

The TCA9535 open-drain interrupt ($\overline{INT}$) output is activated when any input state differs from its corresponding Input Port register state and is used to indicate to the system controller that an input state has changed.

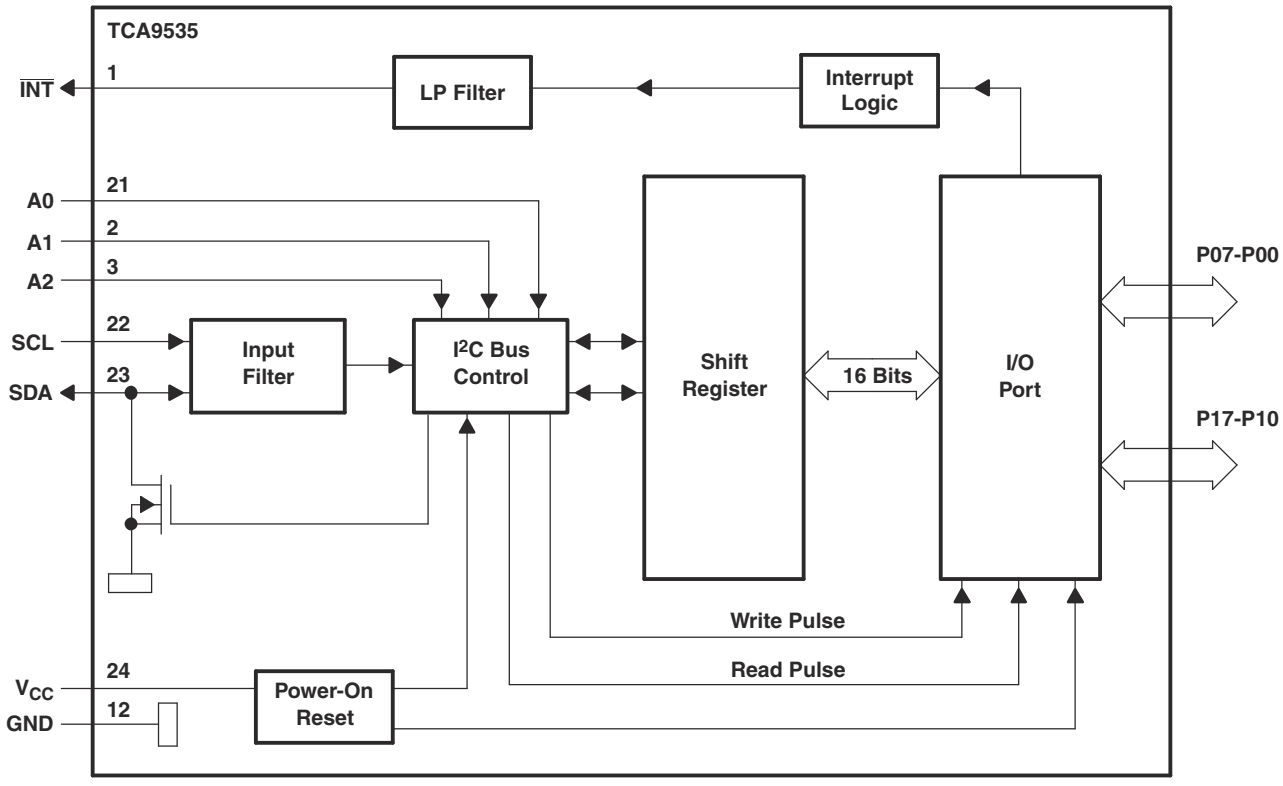
$\overline{INT}$ can be connected to the interrupt input of a microcontroller. By sending an interrupt signal on this line, the remote I/O can inform the microcontroller if there is incoming data on its ports without having to communicate via the I^2C bus. Thus, the TCA9535 can remain a simple target device.

The device outputs (latched) have high-current drive capability for directly driving LEDs. The device has low current consumption.

The TCA9535 device is similar to the PCA9555, except for the removal of the internal I/O pull-up resistor, which greatly reduces power consumption when the I/Os are held low. The TCA9535 is equivalent to the PCA9535 with lower voltage support (down to V_{CC} = 1.65 V), and also improved power-on-reset circuitry for different application scenarios.

Three hardware pins (A0, A1 and A2) are used to program and vary the fixed I^2C address and allow up to 8 devices to share the same I^2C bus or SMBus.

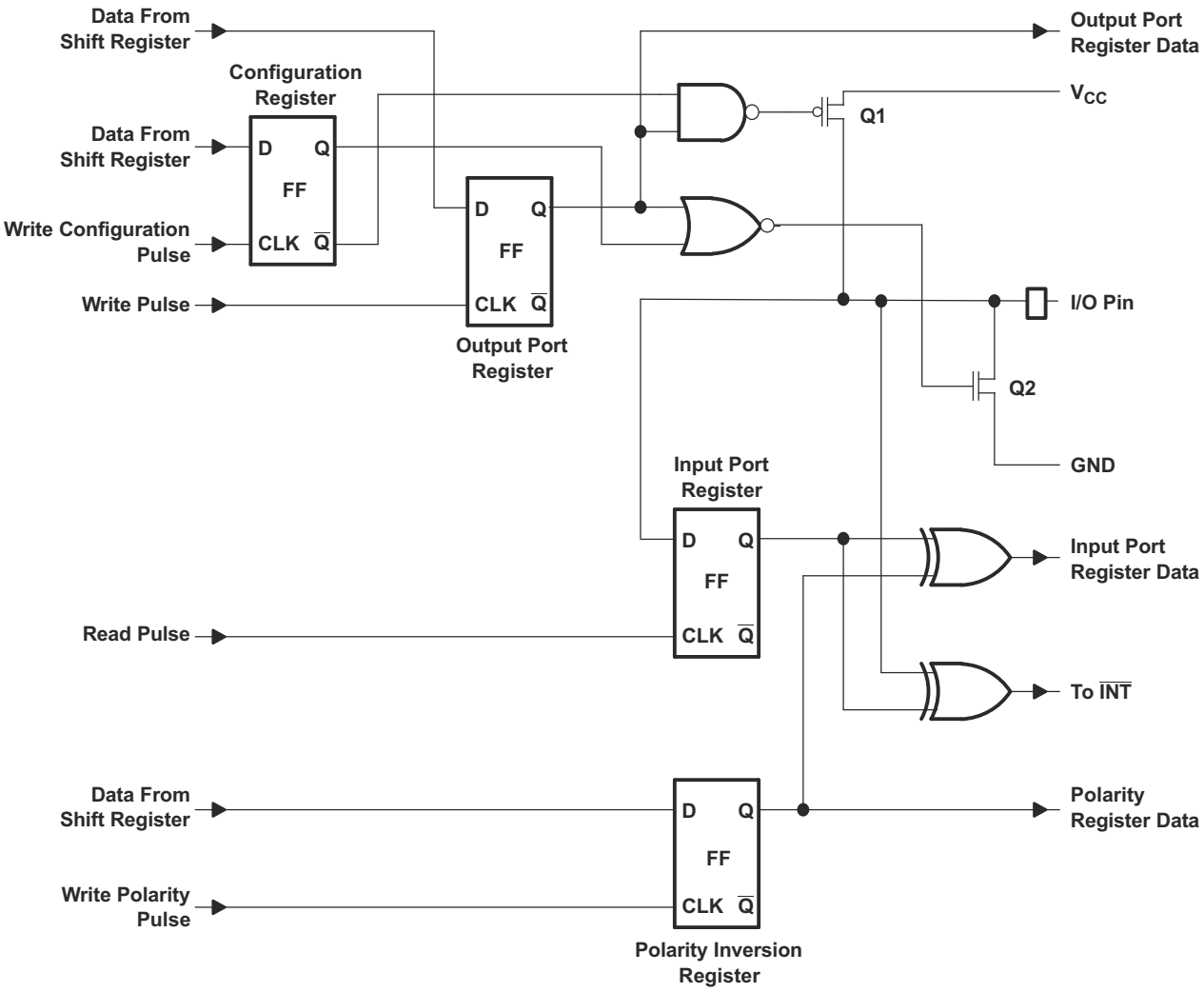
7.2 Functional Block Diagram



Pin numbers shown are for the PW package.

All I/Os are set to inputs at reset.

图 7-1. Logic Diagram (Positive Logic)



At power-on reset, all registers return to default values.

图 7-2. Simplified Schematic of P-Port I/Os

7.3 Feature Description

7.3.1 5-V Tolerant I/O Ports

The TCA9535 features I/O ports, which are tolerant up to 5 V. This allows the TCA9535 to be connected to a large array of devices. To minimize I_{CC}, any input signals must be designed so the input voltage stays within V_{IH} and V_{IL} of the device as described in the *Electrical Characteristics* section.

7.3.2 Hardware Address Pins

The TCA9535 features 3 hardware address pins (A0, A1, and A2). The user selects the device I^2C address by pulling each pin to either V_{CC} or GND to signify the bit value in the address. This allows up to 8 TCA9535 devices to be on the same bus without address conflicts. See the *Functional Block Diagram* for the 3 address pins. The voltage on the pins must not change while the device is powered up in order to prevent possible I^2C glitches as a result of the device address changing during a transmission. All of the pins must be tied either to V_{CC} or GND and cannot be left floating.

7.3.3 Interrupt ($\overline{INT}$) Output

An interrupt is generated by any rising or falling edge of the port inputs in the input mode. After time t_{iv}, the signal $\overline{INT}$ is valid. Resetting the interrupt circuit is achieved when data on the port is changed to the original setting or data is read from the port that generated the interrupt. Resetting occurs in the read mode at the acknowledge (ACK) bit after the rising edge of the SCL signal. Note that the $\overline{INT}$ is reset at the ACK just before the byte of changed data is sent. Interrupts that occur during the ACK clock pulse can be lost (or be very short) because of the resetting of the interrupt during this pulse. Each change of the I/Os after resetting is detected and is transmitted as $\overline{INT}$.

Reading from or writing to another device does not affect the interrupt circuit, and a pin configured as an output cannot cause an interrupt. Changing an I/O from an output to an input may cause a false interrupt to occur if the state of the pin does not match the contents of the Input Port register. Because each 8-bit port is read independently, the interrupt caused by port 0 is not cleared by a read of port 1, or the interrupt caused by port 1 is not cleared by a read of port 0.

$\overline{INT}$ has an open-drain structure. $\overline{INT}$ requires a pull-up resistor to V_{CC} of moderate value (typically about 10 kΩ).

7.4 Device Functional Modes

7.4.1 Power-On Reset (POR)

When power (from 0 V) is applied to V_{CC}, an internal power-on reset circuit holds the TCA9535 in a reset condition until V_{CC} has reached V_{PORR}. At that time, the reset condition is released. The TCA9535 registers and I^2C-SMBus state machine initialize to their default states. Then, V_{CC} must be lowered to below V_{PORF} and back up to the operating voltage for a power-reset cycle.

7.4.2 Powered-Up

When power has been applied to V_{CC} above V_{PORR}, and the POR has taken place, the device is in a functioning mode. In this state, the device is ready to accept any incoming I^2C requests and is monitoring for changes on the input ports.

7.5 Programming

7.5.1 I^2C Interface

The TCA9535 has a standard bidirectional I^2C interface that is controlled by a controller device in order to be configured or read the status of this device. Each target on the I^2C bus has a specific device address to differentiate between other target devices that are on the same I^2C bus. Many target devices require configuration upon startup to set the behavior of the device. This is typically done when the controller accesses internal register maps of the target, which have unique register addresses. A device can have one or multiple registers where data is stored, written, or read. For more information see *Understanding the I^2C Bus* application report, SLVA704.

The physical I^2C interface consists of the serial clock (SCL) and serial data (SDA) lines. Both SDA and SCL lines must be connected to V_{CC} through a pull-up resistor. The size of the pull-up resistor is determined by the amount of capacitance on the I^2C lines. For further details, see *I^2C Pull-up Resistor Calculation* application report, SLVA689. Data transfer may be initiated only when the bus is idle. A bus is considered idle if both SDA and SCL lines are high after a STOP condition. See 表 7-1.

图 7-3 and 图 7-4 show the general procedure for a controller to access a target device:

1. If a controller wants to send data to a target:
   - Controller-transmitter sends a START condition and addresses the target-receiver.
   - Controller-transmitter sends data to target-receiver.
   - Controller-transmitter terminates the transfer with a STOP condition.
2. If a controller wants to receive or read data from a target:
   - Controller-receiver sends a START condition and addresses the target-transmitter.
   - Controller-receiver sends the requested register to read to target-transmitter.

- Controller-receiver receives data from the target-transmitter.
- Controller-receiver terminates the transfer with a STOP condition.

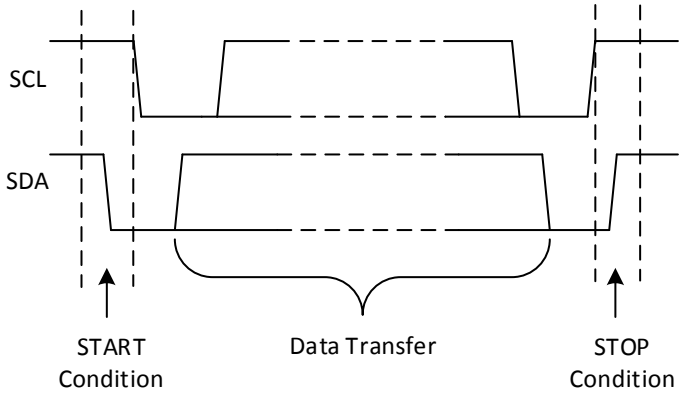


图 7-3. Definition of Start and Stop Conditions

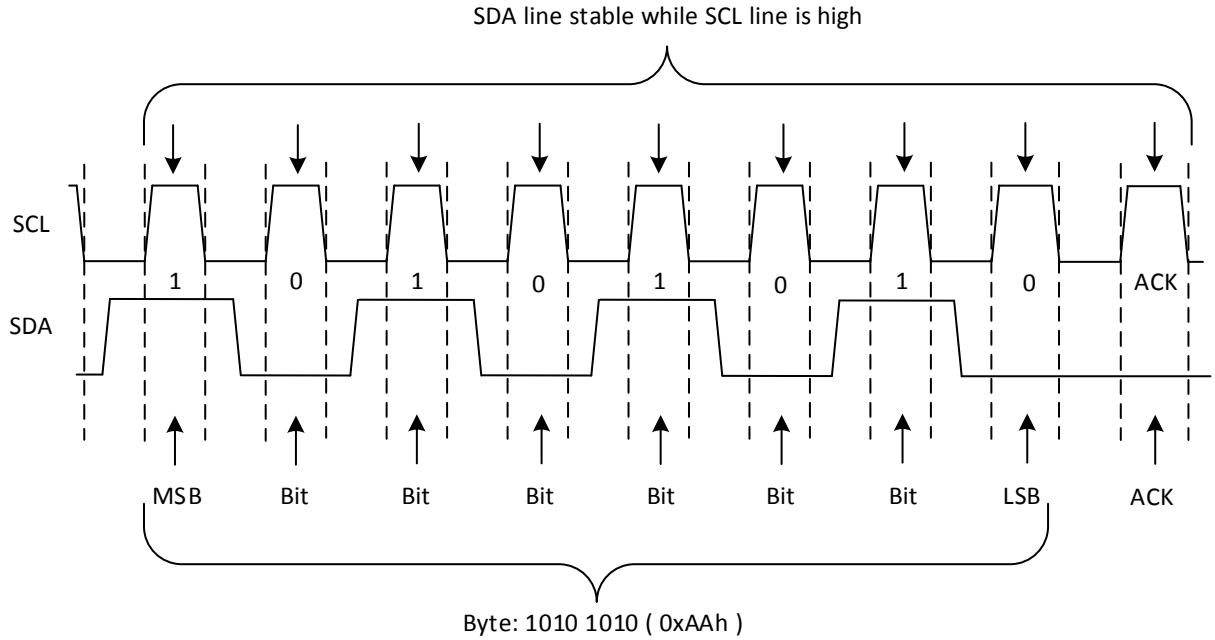


图 7-4. Bit Transfer

表 7-1 shows the interface definition.

表 7-1. Interface Definition

BYTE	BIT							
	7 (MSB)	6	5	4	3	2	1	0 (LSB)
I^2C target address	L	H	L	L	A2	A1	A0	R/ $\overline{W}$
P0x I/O data bus	P07	P06	P05	P04	P03	P02	P01	P00
P1x I/O data bus	P17	P16	P15	P14	P13	P12	P11	P10

7.5.1.1 Bus Transactions

Data is exchanged between the controller and the TCA9535 through write and read commands, and this is accomplished by reading from or writing to registers in the target device.

Registers are locations in the memory of the target which contain information, whether it be the configuration information or some sampled data to send back to the controller. The controller must write information to these registers in order to instruct the target device to perform a task.

7.5.1.1.1 Writes

To write on the I^2C bus, the controller sends a START condition on the bus with the address of the target, as well as the last bit (the R/ $\overline{W}$ bit) set to 0, which signifies a write. After the target sends the acknowledge bit, the controller then sends the register address of the register to which it wishes to write. The target acknowledges again, letting the controller know it is ready. After this, the controller starts sending the register data to the target until the controller has sent all the data necessary (which is sometimes only a single byte), and the controller terminates the transmission with a STOP condition.

See the *Control Register and Command Byte* section to see list of the TCA9535 internal registers and a description of each one.

图 7-5 shows an example of writing a single byte to a target register.

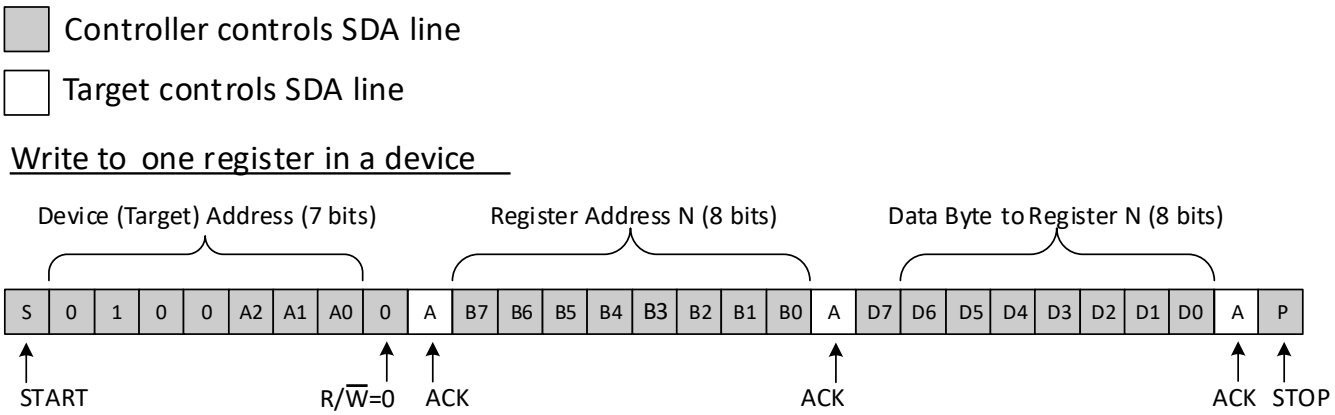


图 7-5. Write to Register

图 7-6 shows the Write to the Polarity Inversion Register.

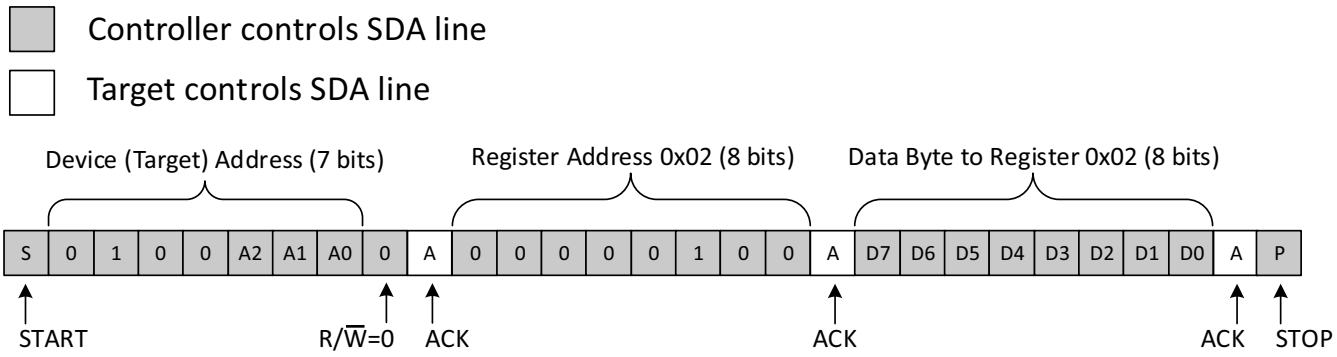


图 7-6. Write to the Polarity Inversion Register

图 7-7 shows the Write to Output Port Registers.

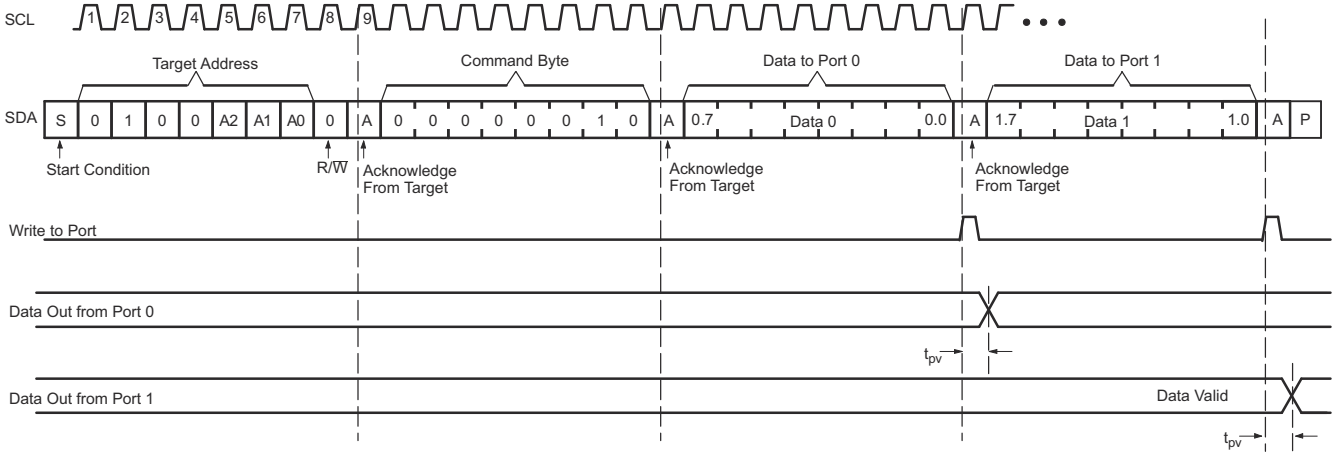


图 7-7. Write to Output Port Registers

7.5.1.1.2 Reads

Reading from a target is very similar to writing, but requires some additional steps. In order to read from a target, the controller must first instruct the target which register it wishes to read from. This is done by the controller starting off the transmission in a similar fashion as the write, by sending the address with the R/ $\overline{W}$ bit equal to 0 (signifying a write), followed by the register address it wishes to read from. When the target acknowledges this register address, the controller sends a START condition again, followed by the target address with the R/ $\overline{W}$ bit set to 1 (signifying a read). This time, the target acknowledges the read request, and the controller releases the SDA bus but continues supplying the clock to the target. During this part of the transaction, the controller becomes the controller-receiver, and the target becomes the target-transmitter.

The controller continues to send out the clock pulses, but releases the SDA line so that the target can transmit data. At the end of every byte of data, the controller sends an ACK to the target, letting the target know that it is ready for more data. When the controller has received the number of bytes it is expecting, it sends a NACK, signaling to the target to halt communications and release the bus. The controller follows this up with a STOP condition.

See the *Control Register and Command Byte* section to see list of the TCA9535's internal registers and a description of each one.

图 7-8 shows an example of reading a single byte from a target register.

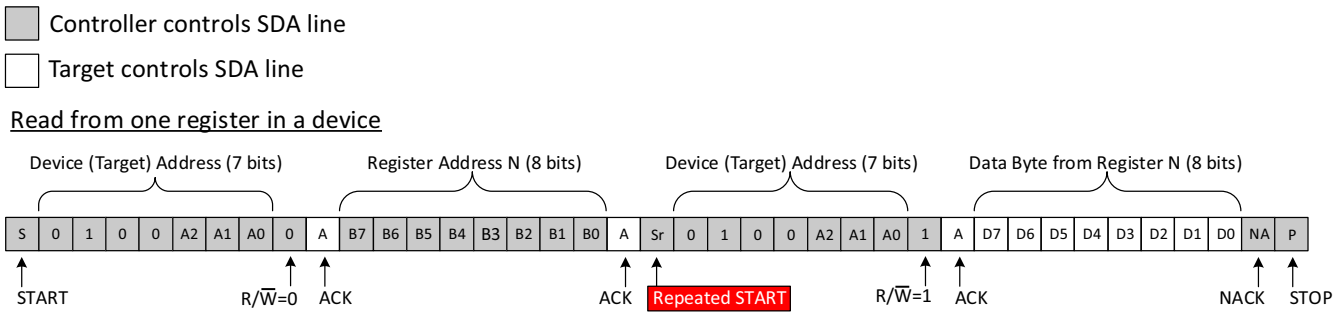
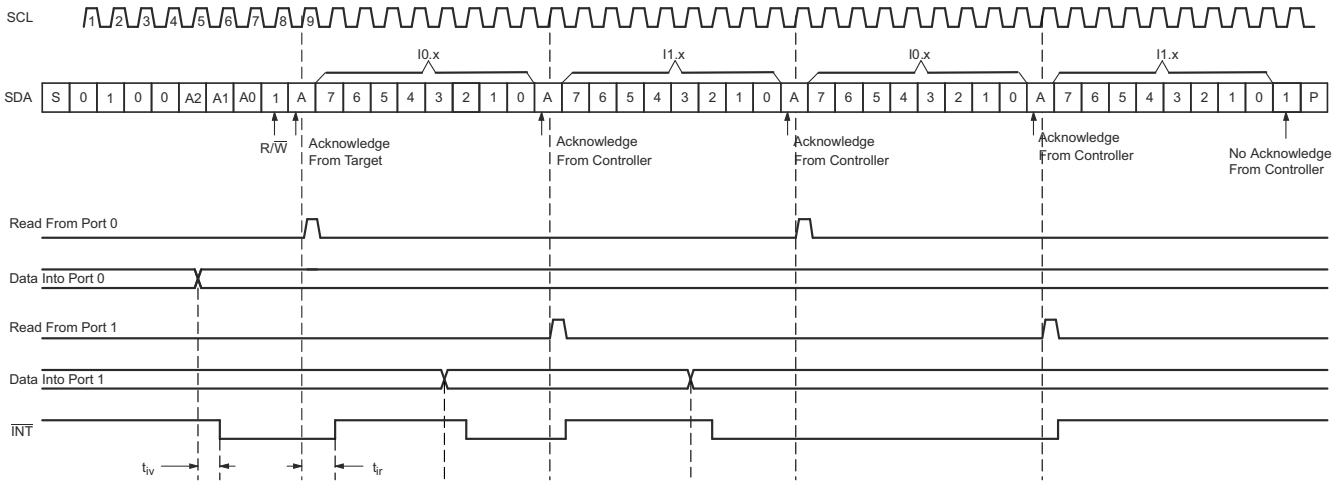


图 7-8. Read from Register

After a restart, the value of the register defined by the command byte matches the register being accessed when the restart occurred. For example, if the command byte references Input Port 1 before the restart, and the restart occurs when Input Port 0 is being read, the stored command byte changes to reference Input Port 0. The original command byte is forgotten. If a subsequent restart occurs, Input Port 0 is read first. Data is clocked into the register on the rising edge of the ACK clock pulse. After the first byte is read, additional bytes may be read, but

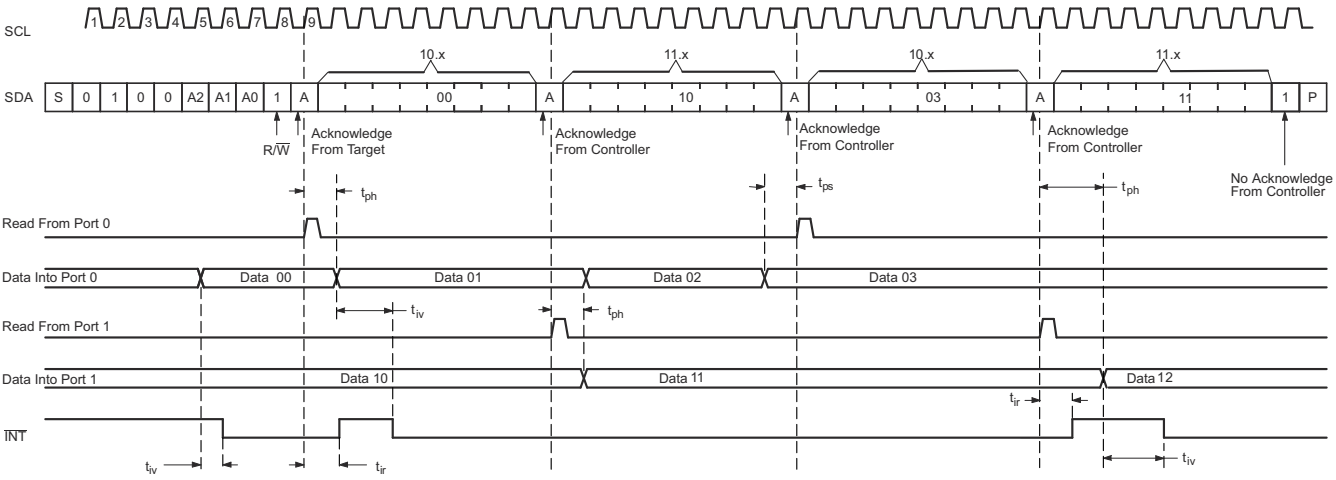
the data now reflect the information in the other register in the pair. For example, if Input Port 1 is read, the next byte read is Input Port 0.

Data is clocked into the register on the rising edge of the ACK clock pulse. There is no limitation on the number of data bytes received in one read transmission, but when the final byte is received, the bus controller must not acknowledge the data. 图 7-9 and 图 7-10 show two different scenarios of Read Input Port Register.



Transfer of data can be stopped at any time by a Stop condition. When this occurs, data present at the latest acknowledge phase is valid (output mode). It is assumed that the command byte previously has been set to 00 (read Input Port register).
This figure eliminates the command byte transfer, a restart, and target address call between the initial target address call and actual data transfer from the P port.

图 7-9. Read Input Port Register, Scenario 1



Transfer of data can be stopped at any time by a Stop condition. When this occurs, data present at the latest acknowledge phase is valid (output mode). It is assumed that the command byte previously has been set to 00 (read Input Port register).
This figure eliminates the command byte transfer, a restart, and target address call between the initial target address call and actual data transfer from the P port.

图 7-10. Read Input Port Register, Scenario 2

7.5.2 Device Address

图 7-11 shows the address byte of the TCA9535.

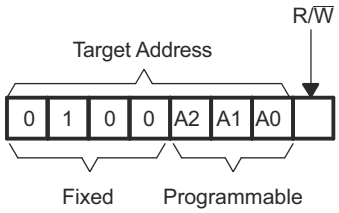


图 7-11. TCA9535 Address

表 7-2 shows the address reference of the TCA9535.

表 7-2. Address Reference

INPUTS			I²C BUS TARGET ADDRESS
A2	A1	A0	
L	L	L	32 (decimal), 0×20 (hexadecimal)
L	L	H	33 (decimal), 0x21 (hexadecimal)
L	H	L	34 (decimal), 0x22 (hexadecimal)
L	H	H	35 (decimal), 0x23 (hexadecimal)
H	L	L	36 (decimal), 0x24 (hexadecimal)
H	L	H	37 (decimal), 0x25 (hexadecimal)
H	H	L	38 (decimal), 0x26 (hexadecimal)
H	H	H	39 (decimal), 0x27 (hexadecimal)

The last bit of the target address defines the operation (read or write) to be performed. A high (1) selects a read operation, while a low (0) selects a write operation.

7.5.3 Control Register and Command Byte

Following the successful acknowledgment of the address byte, the bus controller sends a command byte shown in 表 7-3 that is stored in the control register in the TCA9535. Three bits of this data byte state the operation (read or write) and the internal register (input, output, polarity inversion, or configuration) that is affected. This register can be written or read through the I^2C bus. The command byte is sent only during a write transmission.

When a command byte has been sent, the register that was addressed continues to be accessed by reads until a new command byte has been sent. 图 7-12 shows the control register bits.

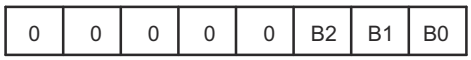


图 7-12. Control Register Bits

表 7-3. Command Byte

CONTROL REGISTER BITS			COMMAND BYTE (HEX)	REGISTER	PROTOCOL	POWER-UP DEFAULT
B2	B1	B0				
0	0	0	0x00	Input Port 0	Read byte	xxxx xxxx
0	0	1	0x01	Input Port 1	Read byte	xxxx xxxx
0	1	0	0x02	Output Port 0	Read-write byte	1111 1111
0	1	1	0x03	Output Port 1	Read-write byte	1111 1111
1	0	0	0x04	Polarity Inversion Port 0	Read-write byte	0000 0000
1	0	1	0x05	Polarity Inversion Port 1	Read-write byte	0000 0000
1	1	0	0x06	Configuration Port 0	Read-write byte	1111 1111
1	1	1	0x07	Configuration Port 1	Read-write byte	1111 1111

7.6 Register Maps

7.6.1 Register Descriptions

The Input Port registers (registers 0 and 1) shown in 表 7-4 reflect the incoming logic levels of the pins, regardless of whether the pin is defined as an input or an output by the Configuration Register. It only acts on read operation. Writes to these registers have no effect. The default value, X, is determined by the externally applied logic level.

Before a read operation, a write transmission is sent with the command byte to let the I^2C device know that the Input Port registers are accessed next.

表 7-4. Registers 0 and 1 (Input Port Registers)

Bit	I0.7	I0.6	I0.5	I0.4	I0.3	I0.2	I0.1	I0.0
Default	X	X	X	X	X	X	X	X
Bit	I1.7	I1.6	I1.5	I1.4	I1.3	I1.2	I1.1	I1.0
Default	X	X	X	X	X	X	X	X

The Output Port registers (registers 2 and 3) shown in 表 7-5 show the outgoing logic levels of the pins defined as outputs by the Configuration register. Bit values in this register have no effect on pins defined as inputs. In turn, reads from this register reflect the value that is in the flip-flop controlling the output selection, not the actual pin value.

表 7-5. Registers 2 and 3 (Output Port Registers)

Bit	O0.7	O0.6	O0.5	O0.4	O0.3	O0.2	O0.1	O0.0
Default	1	1	1	1	1	1	1	1
Bit	O1.7	O1.6	O1.5	O1.4	O1.3	O1.2	O1.1	O1.0
Default	1	1	1	1	1	1	1	1

The Polarity Inversion registers (registers 4 and 5) shown in 表 7-6 allow polarity inversion of pins defined as inputs by the Configuration register. If a bit in this register is set (written with 1), the corresponding pin's polarity is inverted. If a bit in this register is cleared (written with a 0), the corresponding pin's original polarity is retained.

表 7-6. Registers 4 and 5 (Polarity Inversion Registers)

Bit	N0.7	N0.6	N0.5	N0.4	N0.3	N0.2	N0.1	N0.0
Default	0	0	0	0	0	0	0	0
Bit	N1.7	N1.6	N1.5	N1.4	N1.3	N1.2	N1.1	N1.0
Default	0	0	0	0	0	0	0	0

The Configuration registers (registers 6 and 7) shown in 表 7-7 configure the directions of the I/O pins. If a bit in this register is set to 1, the corresponding port pin is enabled as an input with a high-impedance output driver. If a bit in this register is cleared to 0, the corresponding port pin is enabled as an output.

表 7-7. Registers 6 and 7 (Configuration Registers)

Bit	C0.7	C0.6	C0.5	C0.4	C0.3	C0.2	C0.1	C0.0
Default	1	1	1	1	1	1	1	1
Bit	C1.7	C1.6	C1.5	C1.4	C1.3	C1.2	C1.1	C1.0
Default	1	1	1	1	1	1	1	1

8 Application and Implementation

备注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI’s customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

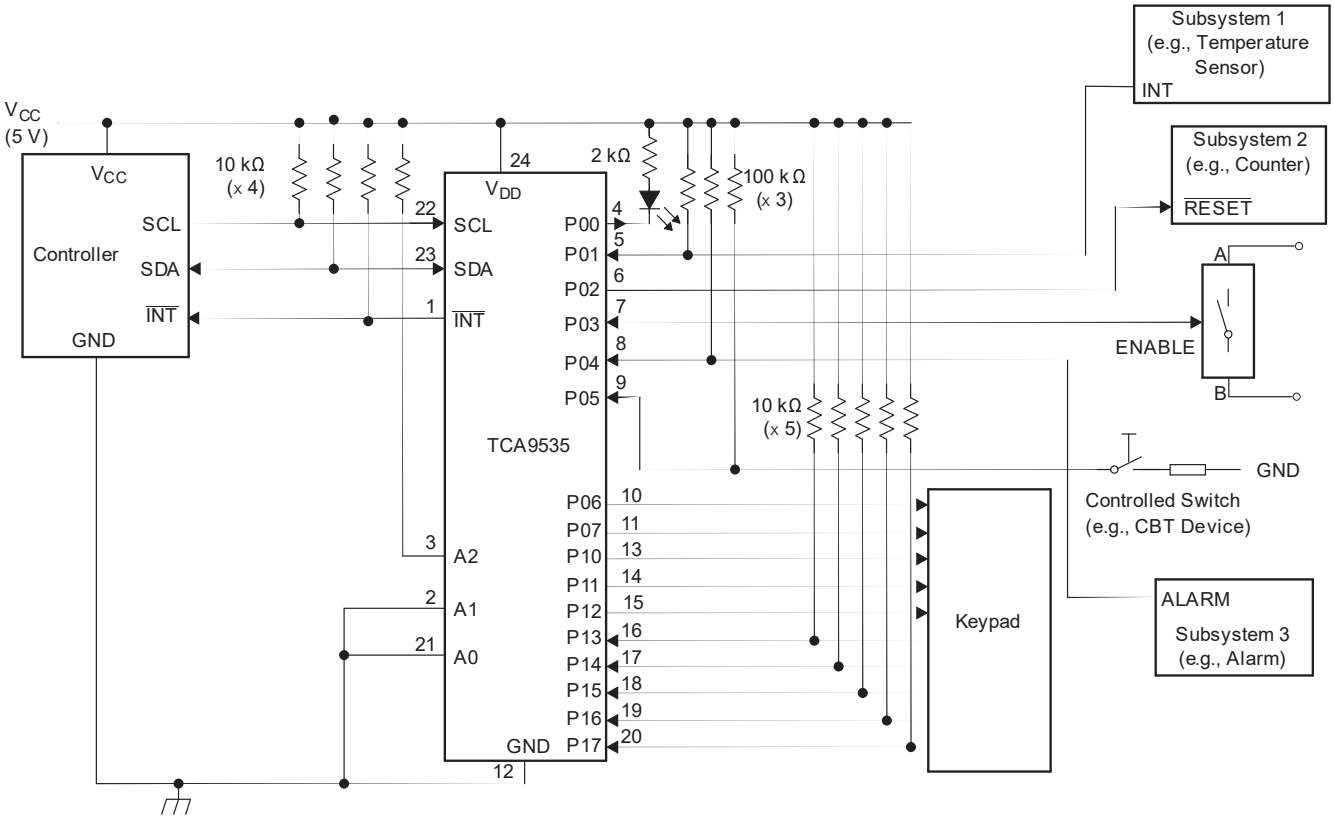
8.1 Application Information

Applications of the TCA9535 has the device connected as a target to an I^2C controller (processor), and the I^2C bus may contain any number of other target devices. The TCA9535 is typically in a remote location from the controller, placed close to the GPIOs to which the controller needs to monitor or control.

IO Expanders such as the TCA9535 are typically used for controlling LEDs (for feedback or status lights), controlling enable or reset signals of other devices, and even reading the outputs of other devices or buttons.

8.2 Typical Application

图 8-1 shows an application in which the TCA9535 can be used.



Device address is configured as 0100100 for this example.
P00, P02, and P03 are configured as outputs.
P01, P04 – P07, and P10 – P17 are configured as inputs.
Pin numbers shown are for the PW package.

图 8-1. Application Schematic

8.2.1 Design Requirements

The designer must take into consideration the system, to be sure not to violate any of the parameters. 表 8-1 shows some key parameters which must not be violated.

表 8-1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
I^2C and Subsystem Voltage (V_{CC})	5 V
Output current rating, P-port sinking (I_{OL})	25 mA
I^2C bus clock (SCL) speed	400 kHz

8.2.1.1 Calculating Junction Temperature and Power Dissipation

When designing with this device, it is important that the *Recommended Operating Conditions* not be violated. Many of the parameters of this device are rated based on junction temperature. So junction temperature must be calculated in order to verify that safe operation of the device is met. The basic equation for junction temperature is shown in 方程式 1.

$$T_j = T_A + (\theta_{JA} \times P_d) \quad (1)$$

θ_{JA} is the standard junction to ambient thermal resistance measurement of the package, as seen in *Thermal Information* table. P_d is the total power dissipation of the device, and the approximation is shown in 方程式 2.

$$P_d \approx (I_{CC\_STATIC} \times V_{CC}) + \sum P_{d\_PORT\_L} + \sum P_{d\_PORT\_H} \quad (2)$$

方程式 2 is the approximation of power dissipation in the device. The equation is the static power plus the summation of power dissipated by each port (with a different equation based on if the port is outputting high, or outputting low. If the port is set as an input, then power dissipation is the input leakage of the pin multiplied by the voltage on the pin). Note that this ignores power dissipation in the $\overline{INT}$ and SDA pins, assuming these transients to be small. They can easily be included in the power dissipation calculation by using 方程式 3 to calculate the power dissipation in $\overline{INT}$ or SDA while they are pulling low, and this gives maximum power dissipation.

$$P_{d\_PORT\_L} = (I_{OL} \times V_{OL}) \quad (3)$$

方程式 3 shows the power dissipation for a single port which is set to output low. The power dissipated by the port is the V_{OL} of the port multiplied by the current it is sinking.

$$P_{d\_PORT\_H} = (I_{OH} \times (V_{CC} - V_{OH})) \quad (4)$$

方程式 4 shows the power dissipation for a single port which is set to output high. The power dissipated by the port is the current sourced by the port multiplied by the voltage drop across the device (difference between V_{CC} and the output voltage).

8.2.1.2 Minimizing I_{CC} When I/O is Used to Control LED

When an I/O is used to control an LED, normally it is connected to V_{CC} through a resistor as shown in 图 8-1. Because the LED acts as a diode, when the LED is off, the I/O V_{IN} is about 1.2 V less than V_{CC}. The ΔI_{CC} parameter in the *Electrical Characteristics* table shows how I_{CC} increases as V_{IN} becomes lower than V_{CC}. For battery-powered applications, it is essential that the voltage of I/O pins is greater than or equal to V_{CC} when the LED is off to minimize current consumption.

图 8-2 shows a high-value resistor in parallel with the LED. 图 8-3 shows V_{CC} less than the LED supply voltage by at least 1.2 V. Both of these methods maintain the I/O V_{IN} at or above V_{CC} and prevent additional supply current consumption when the LED is off.

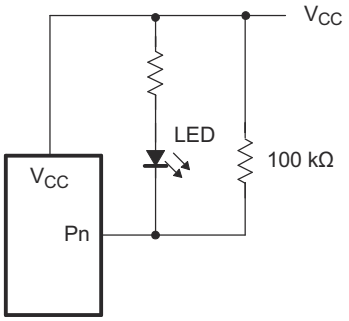


图 8-2. High-Value Resistor in Parallel With LED

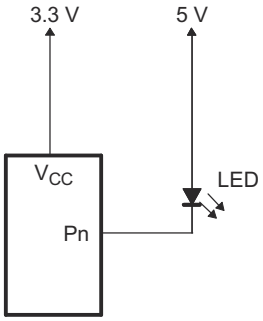


图 8-3. Device Supplied by Lower Voltage

8.2.2 Detailed Design Procedure

The pull-up resistors, R_P, for the SCL and SDA lines need to be selected appropriately and take into consideration the total capacitance of all targets on the I^2C bus. The minimum pull-up resistance is a function of V_{CC}, $V_{OL,(max)}$, and I_{OL} as shown in 方程式 5.

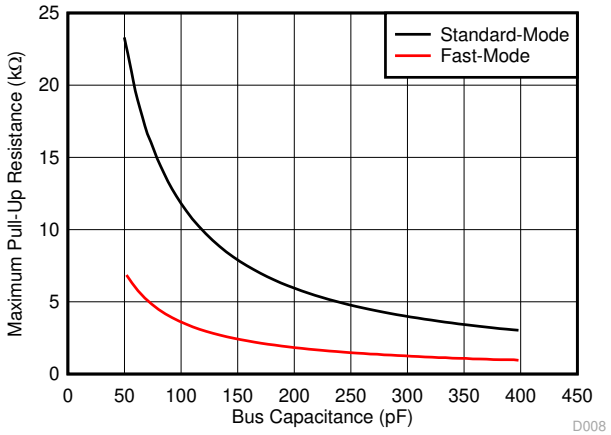
$$R_{p(min)} = \frac{V_{CC} - V_{OL(max)}}{I_{OL}} \quad (5)$$

The maximum pull-up resistance is a function of the maximum rise time, t_r (300 ns for fast-mode operation, f_{SCL} = 400 kHz) and bus capacitance, C_b as shown in 方程式 6.

$$R_{p(max)} = \frac{t_r}{0.8473 \times C_b} \quad (6)$$

The maximum bus capacitance for an I^2C bus must not exceed 400 pF for standard-mode or fast-mode operation. The bus capacitance can be approximated by adding the capacitance of the TCA9535, C_i for SCL or C_{IO} for SDA, the capacitance of wires/connections/traces, and the capacitance of additional targets on the bus. For further details, refer to *I^2C Pull-up Resistor Calculation* application report, SLVA689.

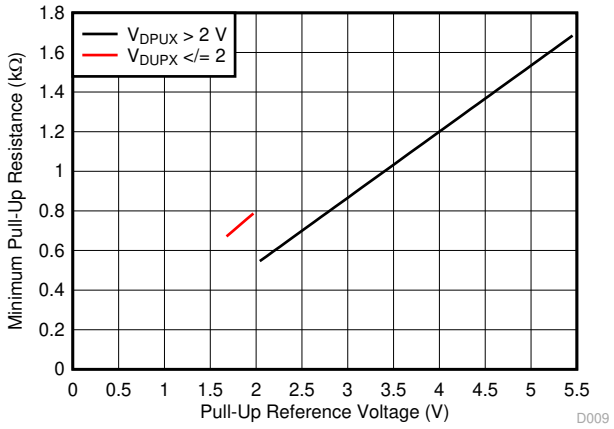
8.2.3 Application Curves



Standard-mode: f_{SCL} = 100 kHz, t_r = 1 µs

Fast-mode: f_{SCL} = 400 kHz, t_r = 300 ns

图 8-4. Maximum Pull-Up Resistance ($R_{p(max)}$) vs Bus Capacitance (C_b)



V_{OL} = 0.2 × V_{CC}, I_{OL} = 2 mA when $V_{CC} \leqslant$ 2 V

V_{OL} = 0.4 V, I_{OL} = 3 mA when V_{CC} > 2 V

图 8-5. Minimum Pull-Up Resistance ($R_{p(min)}$) vs Pull-Up Reference Voltage (V_{CC})

9 Power Supply Recommendations

In the event of a glitch or data corruption, TCA9535 can be reset to its default conditions by using the power-on reset feature. Power-on reset requires that the device go through a power cycle to be completely reset. This reset also happens when the device is powered on for the first time in an application.

The two types of power-on reset are shown in 图 9-1 and 图 9-2.

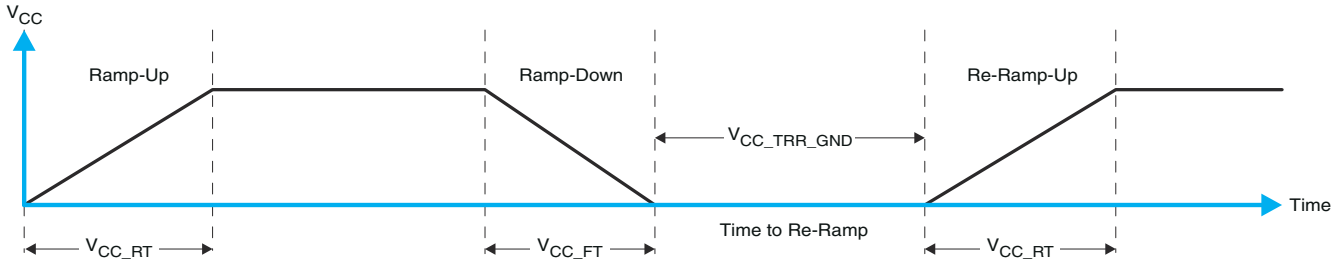


图 9-1. V_{CC} Is Lowered Below 0.2 V Or 0 V And Then Ramped Up To V_{CC}

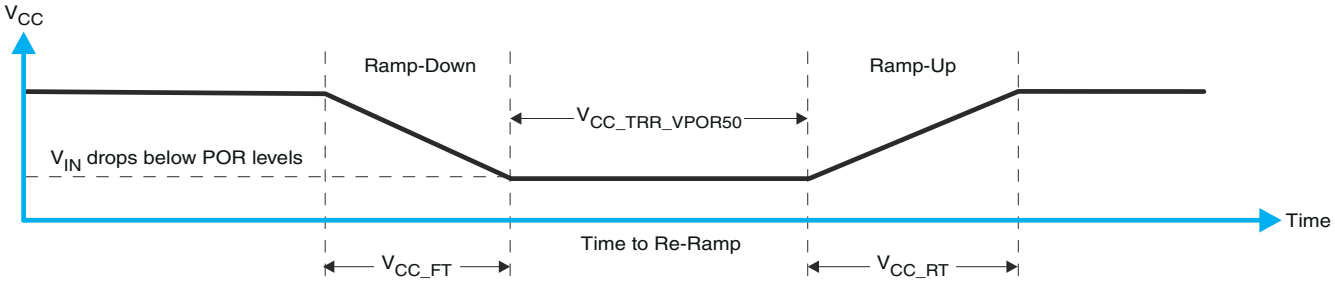


图 9-2. V_{CC} Is Lowered Below The Por Threshold, Then Ramped Back Up To V_{CC}

表 9-1 specifies the performance of the power-on reset feature for TCA9535 for both types of power-on reset.

表 9-1. Recommended Supply Sequencing And Ramp Rates

PARAMETER(1)			MIN	TYP	MAX	UNIT
V_{CC_FT}	Fall rate	See 图 9-1	0.1			ms
V_{CC_RT}	Rise rate	See 图 9-1	0.01			ms
V_{CC_TRR}	Time to re-ramp (when V_{CC} drops to V_{VOR_MIN} – 50 mV or when V_{CC} drops to GND)	See 图 9-1	1			µs
V_{CC_GH}	The level (referenced to V_{CC}) that V_{CC} can glitch down to, but not cause a functional disruption when V_{CC_GW}	See 图 9-3			1.2	V
V_{CC_MV}	The minimum voltage that V_{CC} can glitch down to without causing a reset (V_{CC_GH} must not be violated)	See 图 9-3	1.5			V
V_{CC_GW}	Glitch width that will not cause a functional disruption	See 图 9-3			10	µs
V_{PORF}	Voltage trip point of POR on falling V_{CC}		0.75	1	1	V
V_{PORR}	Voltage trip point of POR on rising V_{CC}			1.2	1.5	V

(1) T_A = –40°C to 85°C (unless otherwise noted)

Glitches in the power supply can also affect the power-on reset performance of this device. The glitch width (V_{CC_GW}) and height (V_{CC_GH}) are dependent on each other. The bypass capacitance, source impedance, and device impedance are factors that affect power-on reset performance. 图 9-3 and 表 9-1 provide more information on how to measure these specifications.

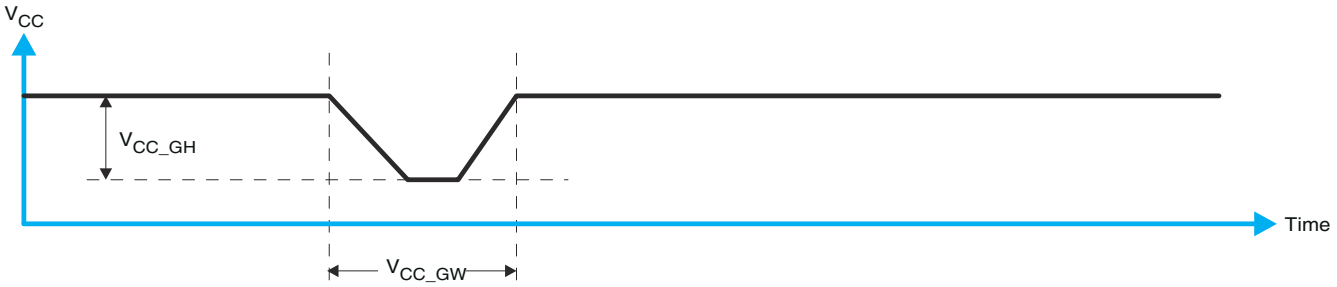


图 9-3. Glitch Width And Glitch Height

V_{PORR} is critical to the power-on reset. V_{PORR} is the voltage level at which the reset condition is released and all the registers and the I^2C/SMBus state machine are initialized to their default states. The value of V_{POR} differs based on the V_{CC} being lowered to or from 0. 图 9-4 and 表 9-1 provide more details on this specification.

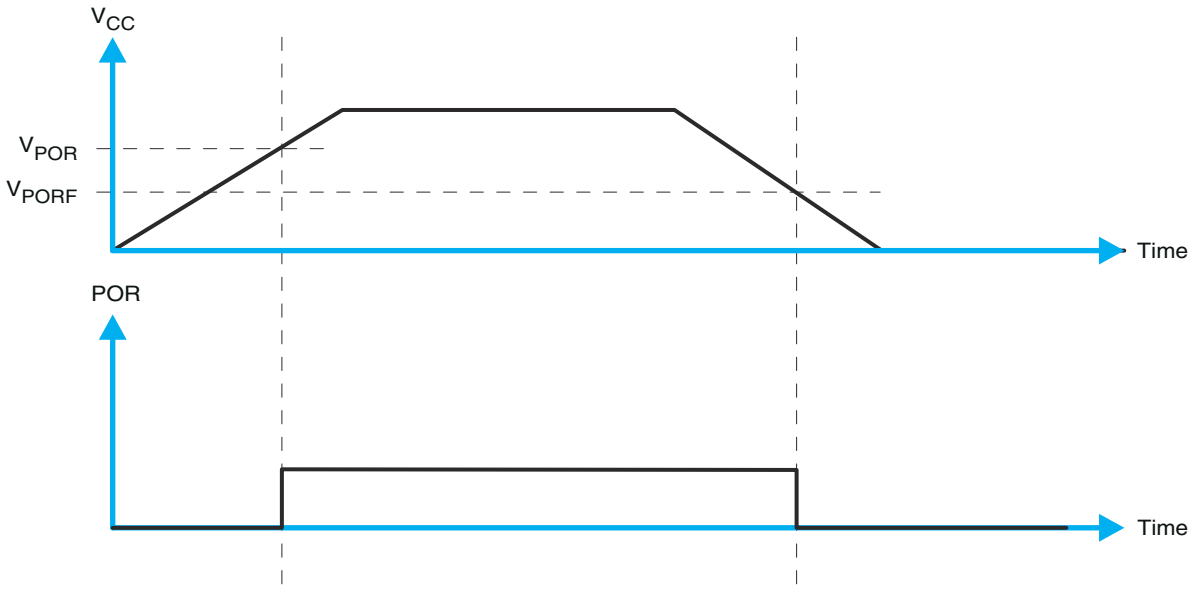


图 9-4. V_{POR}

10 Layout

10.1 Layout Guidelines

For printed circuit board (PCB) layout of the TCA9535, common PCB layout practice must be followed, but additional concerns related to high-speed data transfer such as matched impedances and differential pairs are not a concern for I^2C signal speeds.

In all PCB layouts, it is a best practice to avoid right angles in signal traces, to fan out signal traces away from each other upon leaving the vicinity of an integrated circuit (IC), and to use thicker trace widths to carry higher amounts of current that commonly pass through power and ground traces. By-pass and de-coupling capacitors are commonly used to control the voltage on the V_{CC} pin, using a larger capacitor to provide additional power in the event of a short power supply glitch and a smaller capacitor to filter out high-frequency ripple. These capacitors must be placed as close to the TCA9535 as possible. These best practices are shown in the *Layout Example*.

For the layout example provided in the *Layout Example*, it must be possible to fabricate a PCB with only 2 layers by using the top layer for signal routing and the bottom layer as a split plane for power (V_{CC}) and ground (GND). However, a 4 layer board is preferable for boards with higher density signal routing. On a 4 layer PCB, it is common to route signals on the top and bottom layer, dedicate one internal layer to a ground plane, and dedicate the other internal layer to a power plane. In a board layout using planes or split planes for power and ground, vias are placed directly next to the surface mount component pad which needs to attach to V_{CC}, or GND and the via is connected electrically to the internal layer or the other side of the board. Vias are also used when a signal trace needs to be routed to the opposite side of the board, but this technique is not demonstrated in the *Layout Example*.

10.2 Layout Example

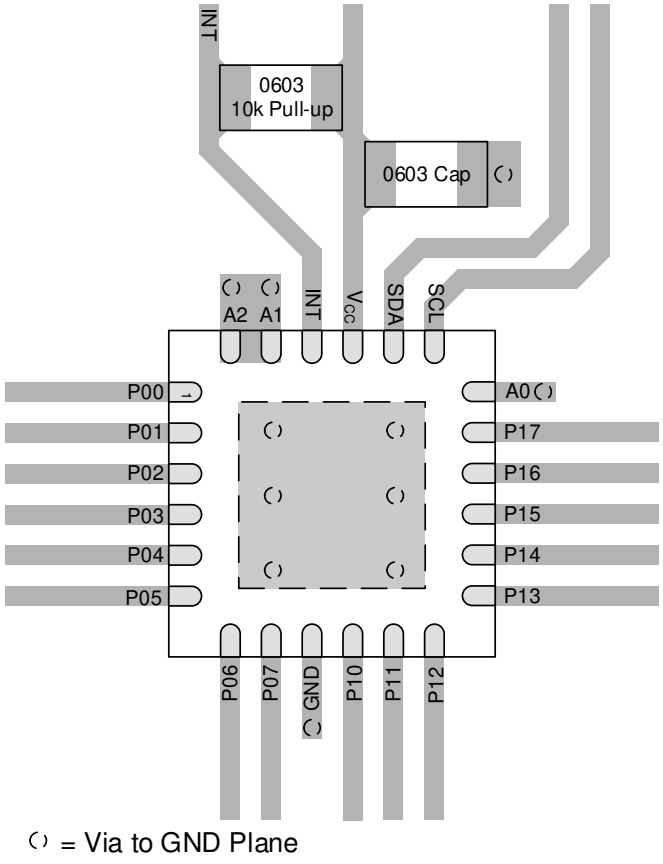


图 10-1. TCA9535 Layout Example

11 Device and Documentation Support

11.1 Documentation Support

11.1.1 Related Documentation

For related documentation see the following:

- *I2C Bus Pull-Up Resistor Calculation*, SLVA689
- *Maximum Clock Frequency of I2C Bus Using Repeaters*, SLVA695
- *Introduction to Logic*, SLVA700
- *Understanding the I2C Bus*, SLVA704
- *IO Expander EVM User's Guide*, SLVUA59A

11.2 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 *订阅更新* 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

11.3 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

11.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
所有商标均为其各自所有者的财产。

11.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.6 术语表

TI 术语表　　本术语表列出并解释了术语、首字母缩略词和定义。

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TCA9535DBR	ACTIVE	SSOP	DB	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TD9535	Samples
TCA9535DBT	ACTIVE	SSOP	DB	24	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	TD9535	Samples
TCA9535MRGER	ACTIVE	VQFN	RGE	24	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TD9535	Samples
TCA9535PWR	ACTIVE	TSSOP	PW	24	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	PW535	Samples
TCA9535RGER	ACTIVE	VQFN	RGE	24	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TD9535	Samples
TCA9535RTWR	ACTIVE	WQFN	RTW	24	3000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	PW535	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

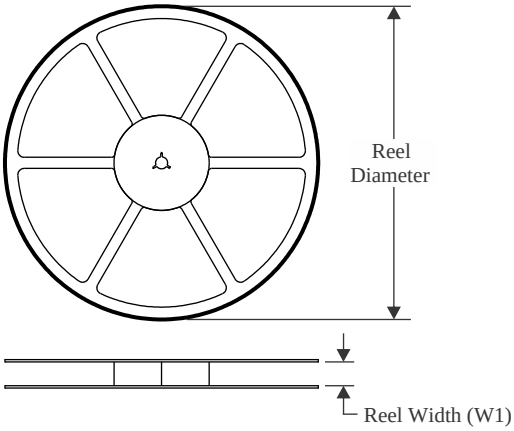
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

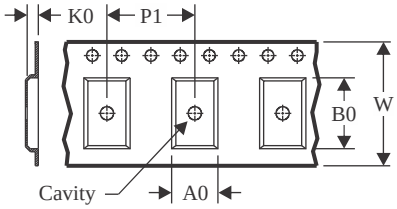
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

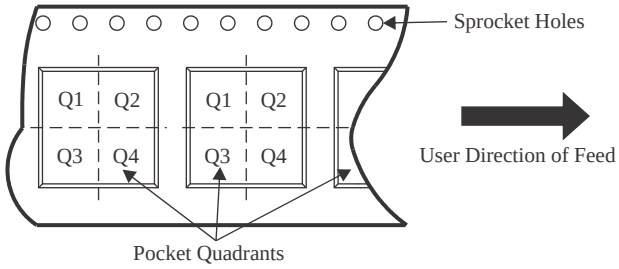


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

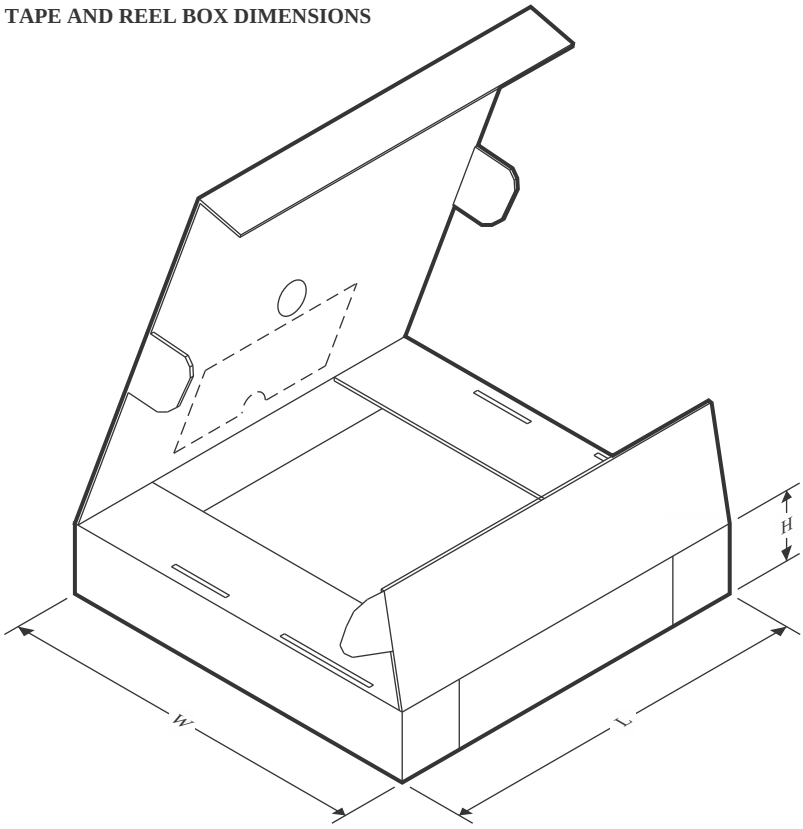
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TCA9535DBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
TCA9535DBT	SSOP	DB	24	250	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
TCA9535MRGER	VQFN	RGE	24	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
TCA9535PWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
TCA9535RGER	VQFN	RGE	24	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
TCA9535RTWR	WQFN	RTW	24	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS



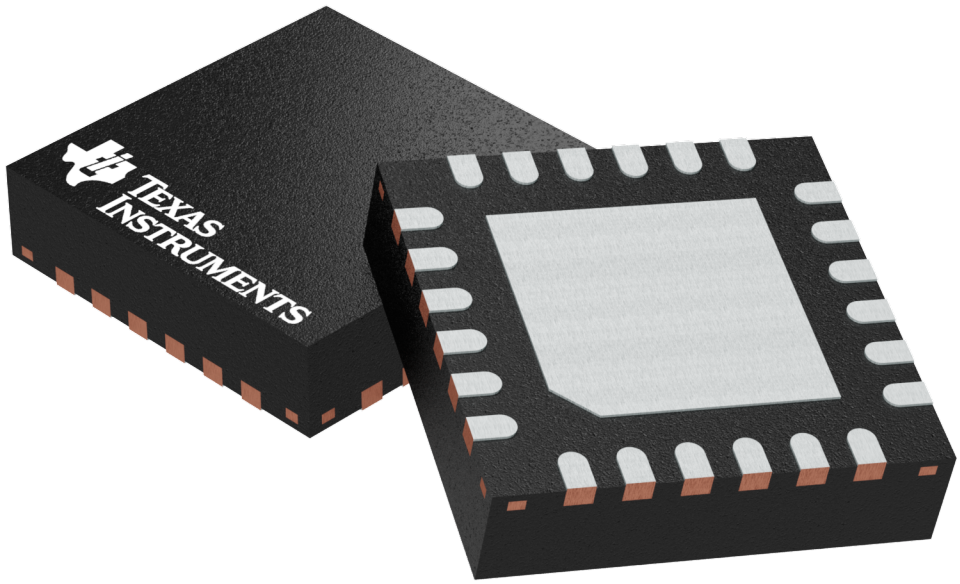
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TCA9535DBR	SSOP	DB	24	2000	356.0	356.0	35.0
TCA9535DBT	SSOP	DB	24	250	356.0	356.0	35.0
TCA9535MRGER	VQFN	RGE	24	3000	367.0	367.0	35.0
TCA9535PWR	TSSOP	PW	24	2000	356.0	356.0	35.0
TCA9535RGER	VQFN	RGE	24	3000	367.0	367.0	35.0
TCA9535RTWR	WQFN	RTW	24	3000	356.0	356.0	35.0

GENERIC PACKAGE VIEW

RGE 24 VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

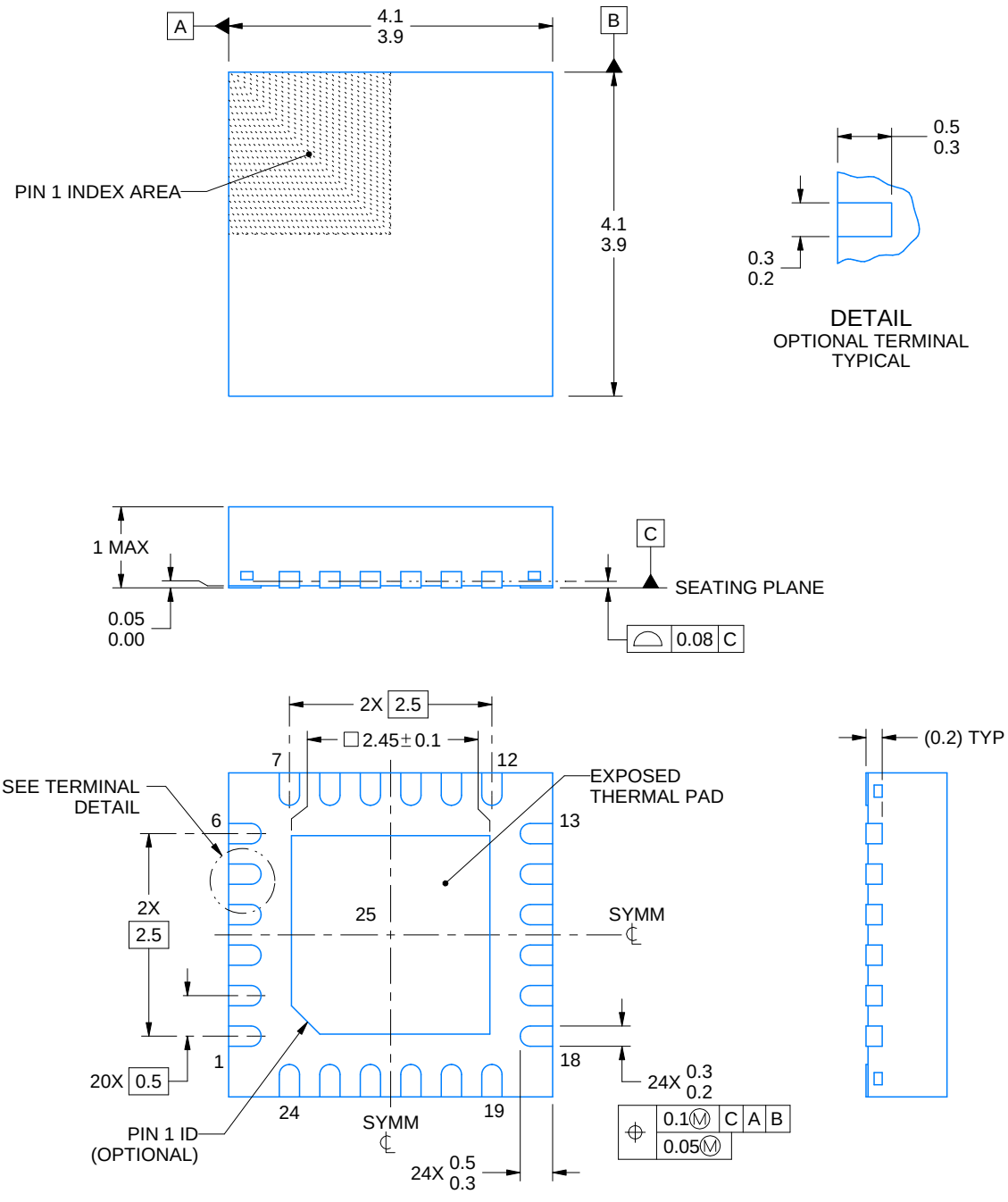
4204104/H

PACKAGE OUTLINE

RGE0024B

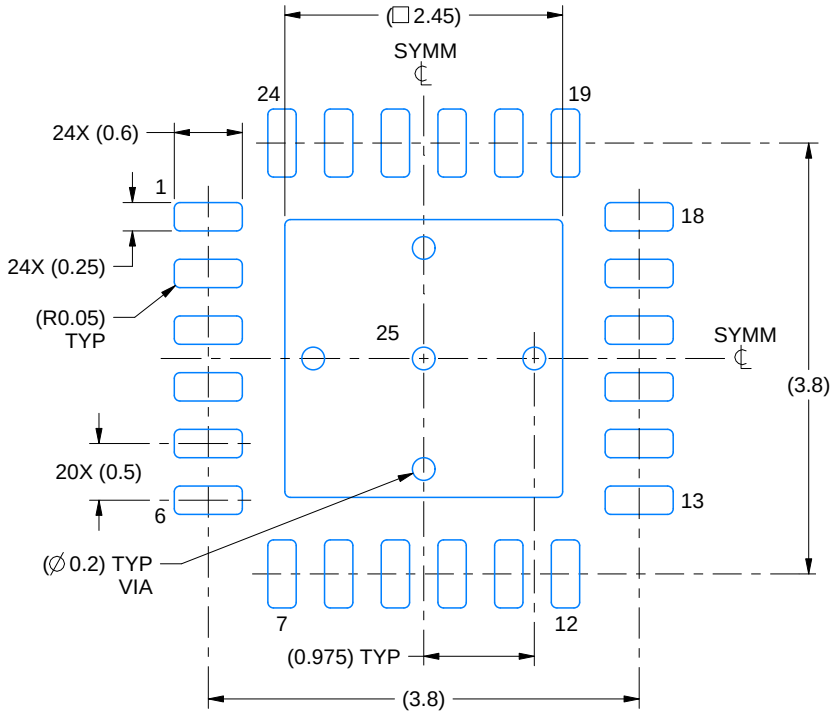
VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

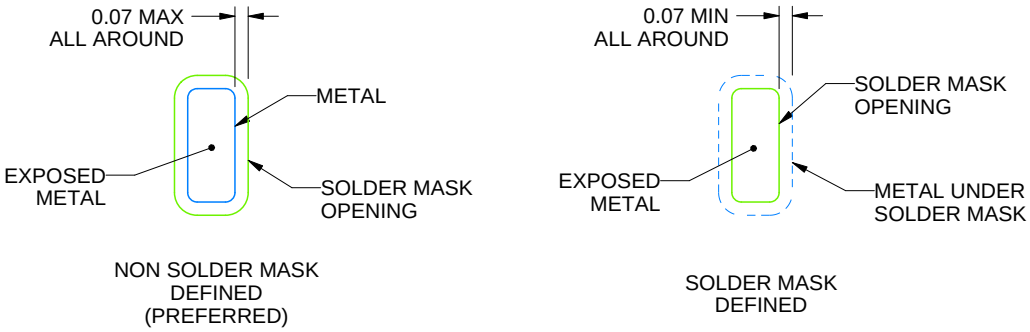


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X

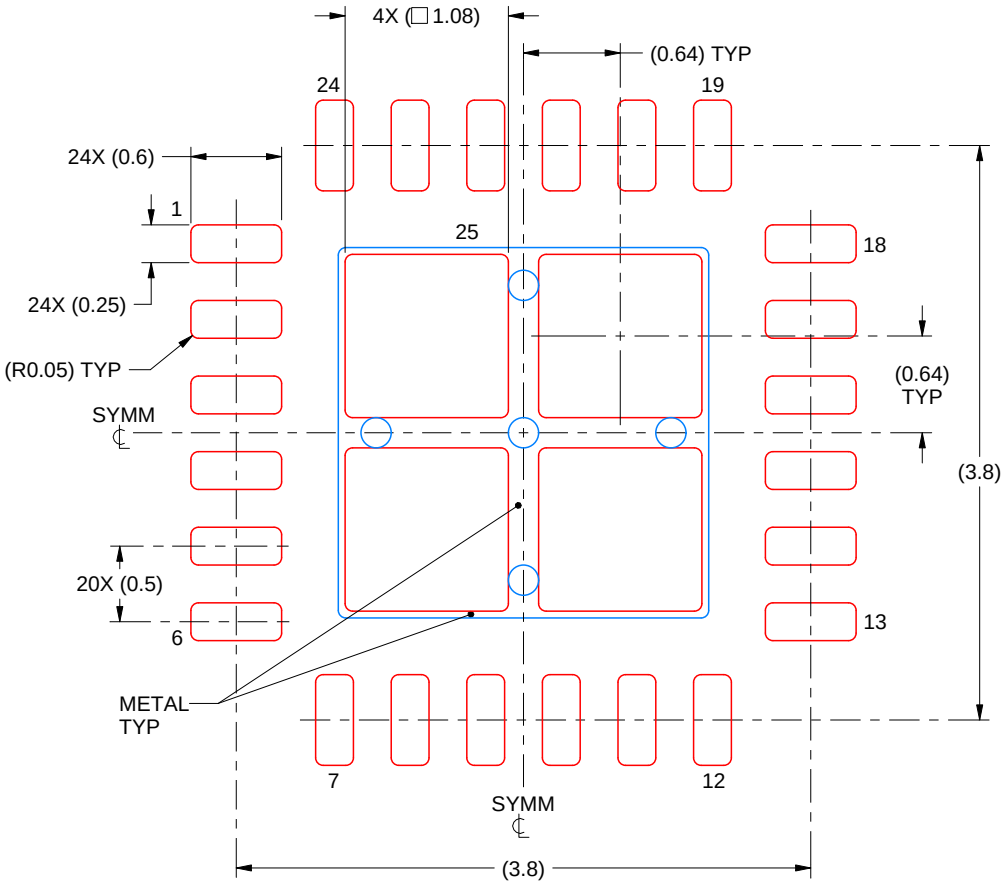


SOLDER MASK DETAILS

4219013/A 05/2017

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 25
78% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:20X

4219013/A 05/2017

NOTES: (continued)

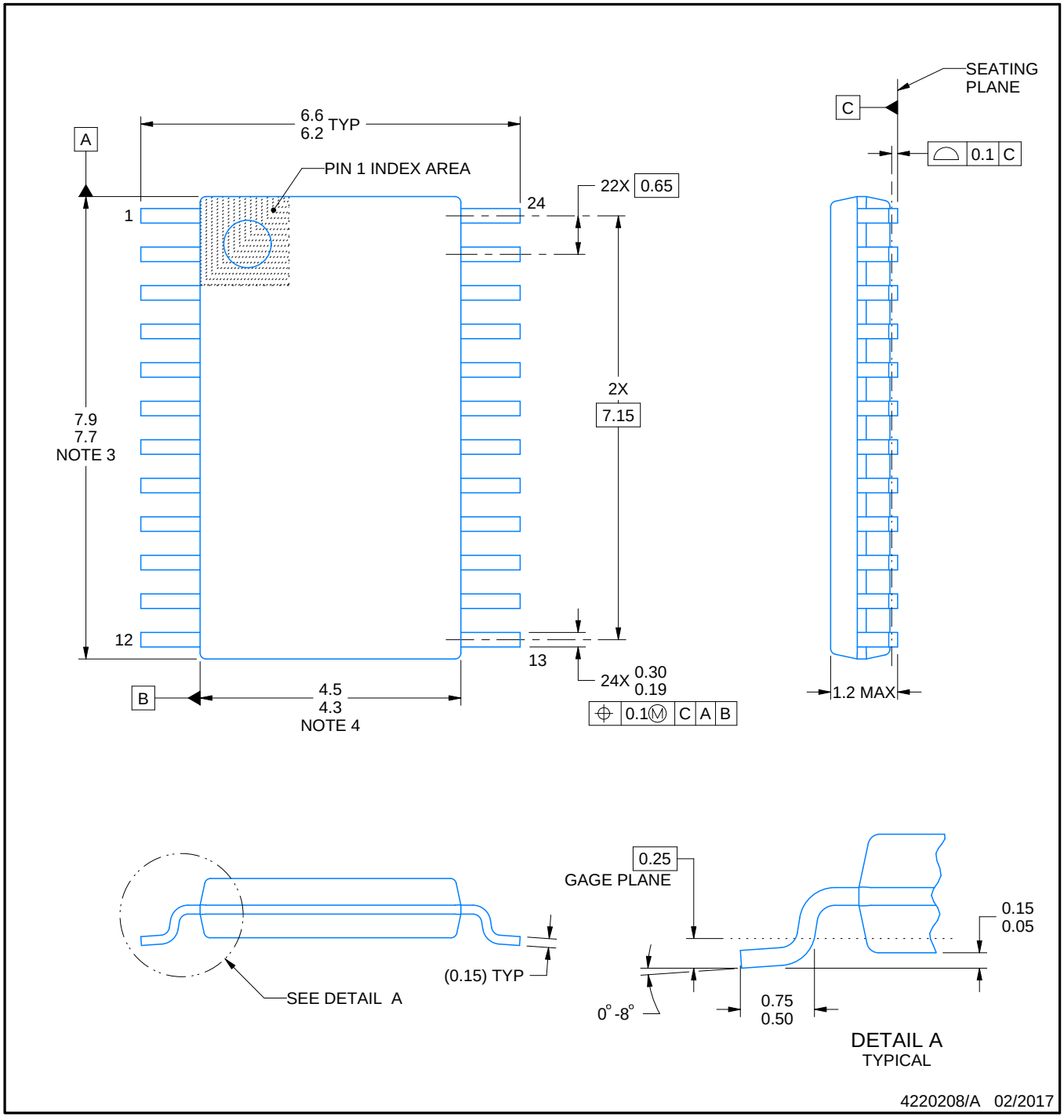
6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

PACKAGE OUTLINE

PW0024A

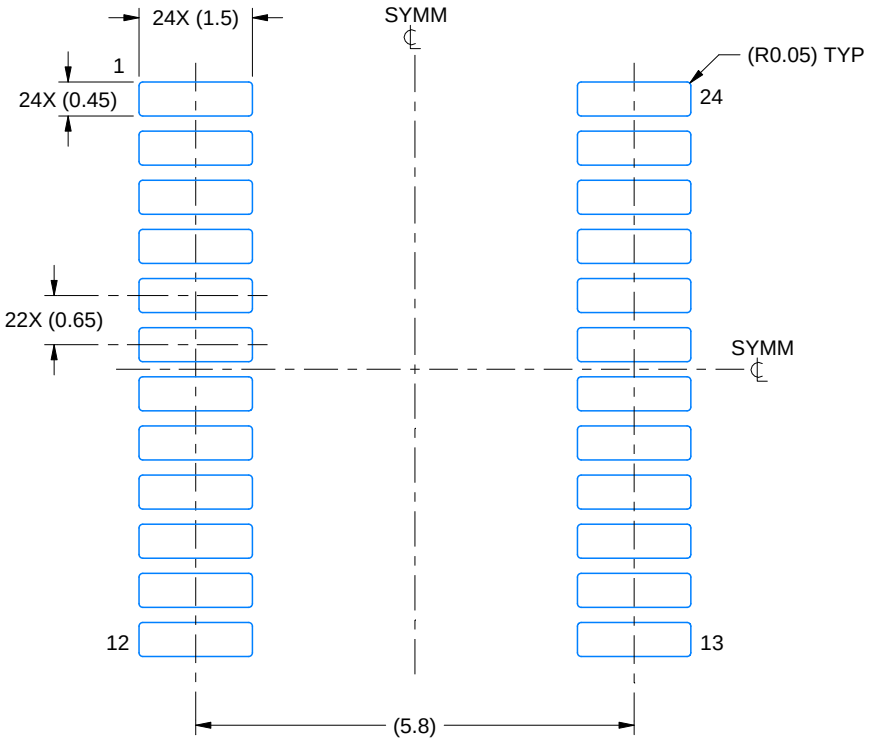
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

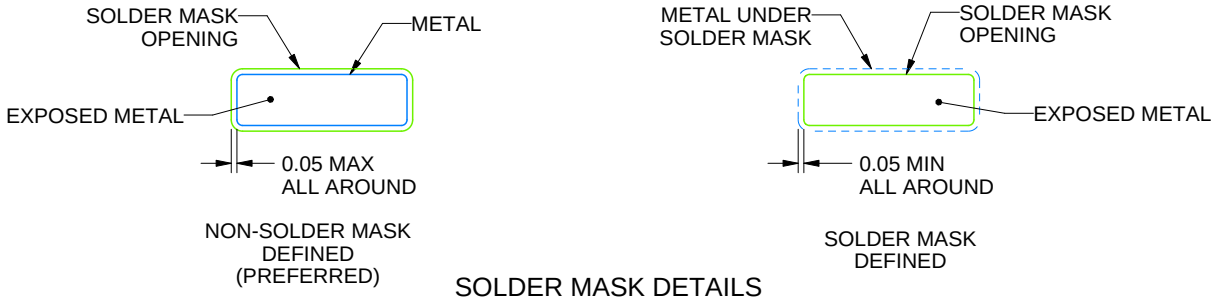


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

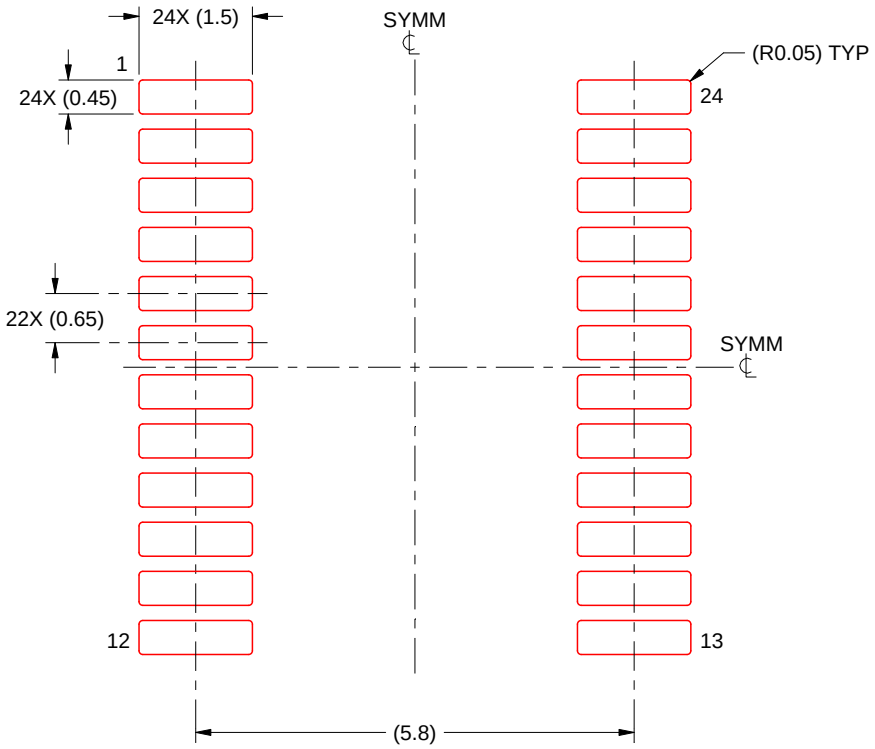


SOLDER MASK DETAILS

4220208/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220208/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

GENERIC PACKAGE VIEW

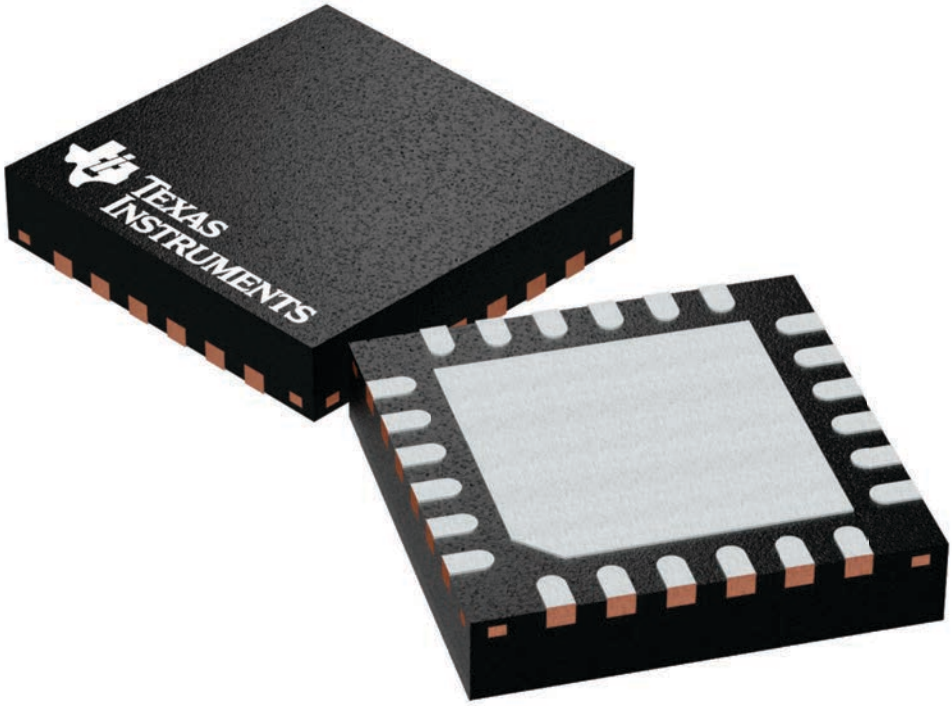
RTW 24

WQFN - 0.8 mm max height

4 x 4, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



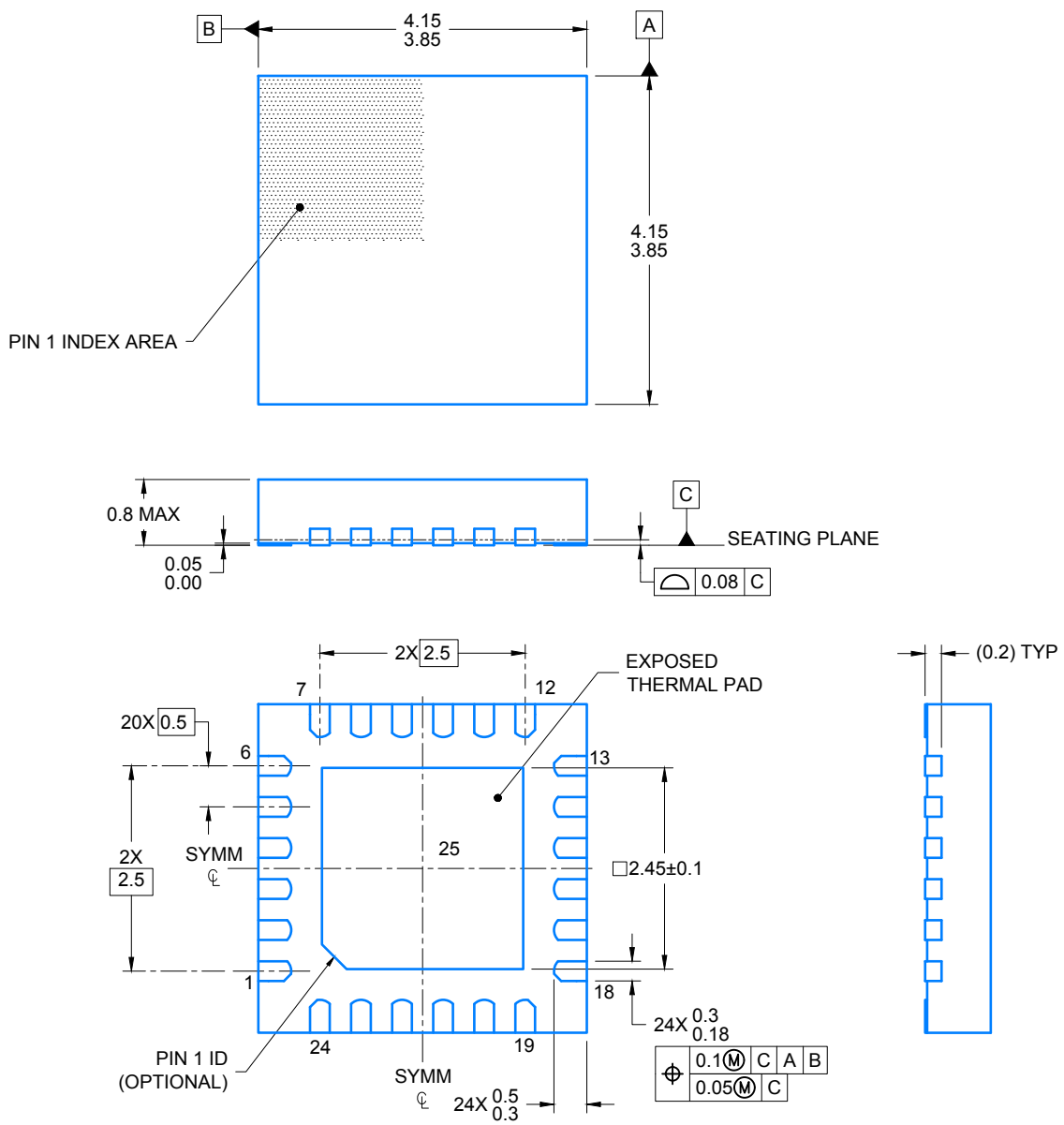
4224801/A

PACKAGE OUTLINE

RTW0024B

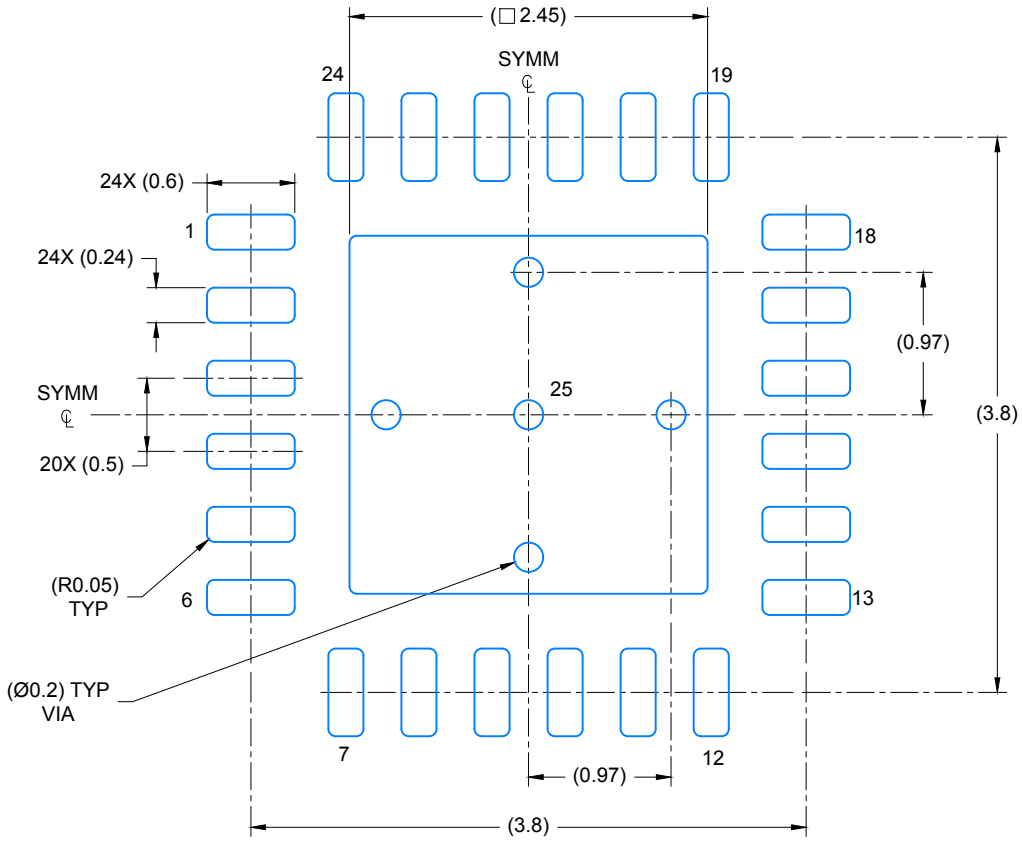
WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK-NO LEAD

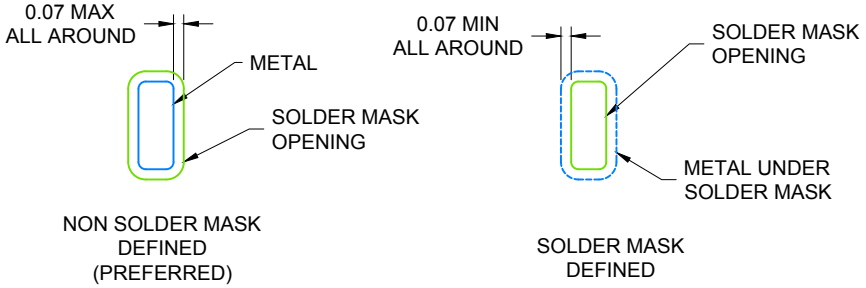


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
SCALE: 20X

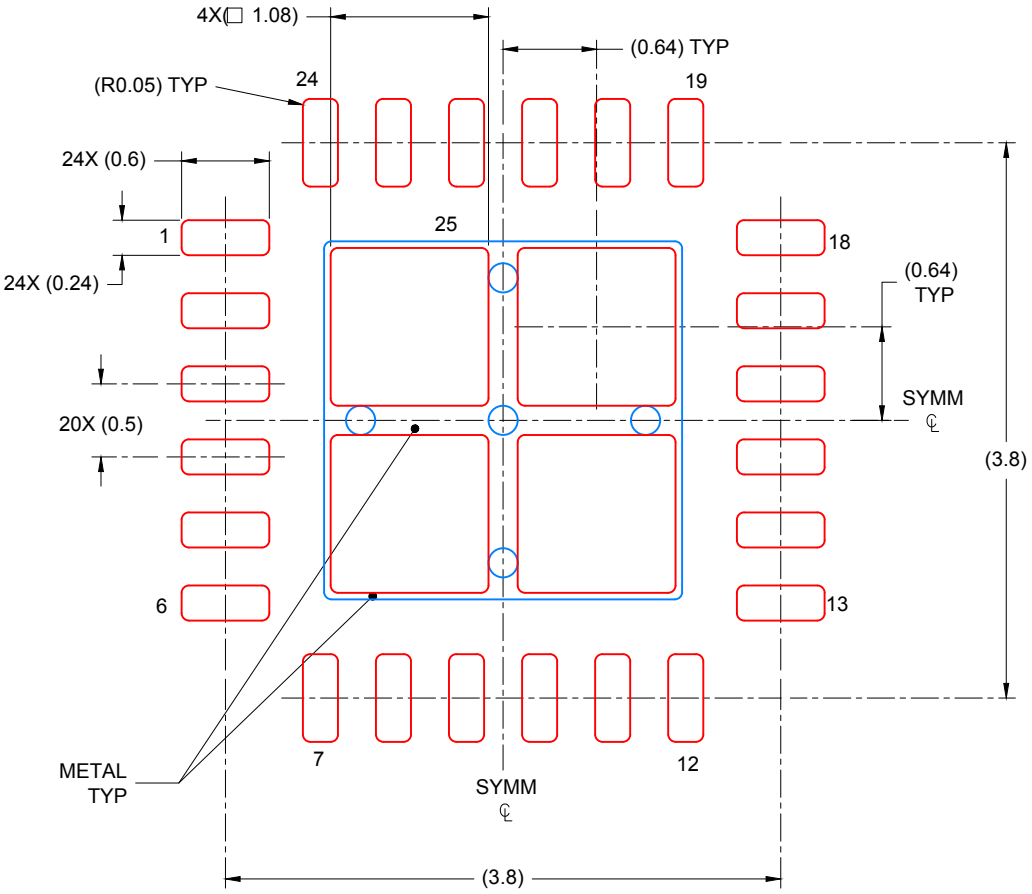


SOLDER MASK DETAILS

4219135/B 11/2016

NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 25:
78% PRINTED COVERAGE BY AREA UNDER PACKAGE
SCALE: 20X

4219135/B 11/2016

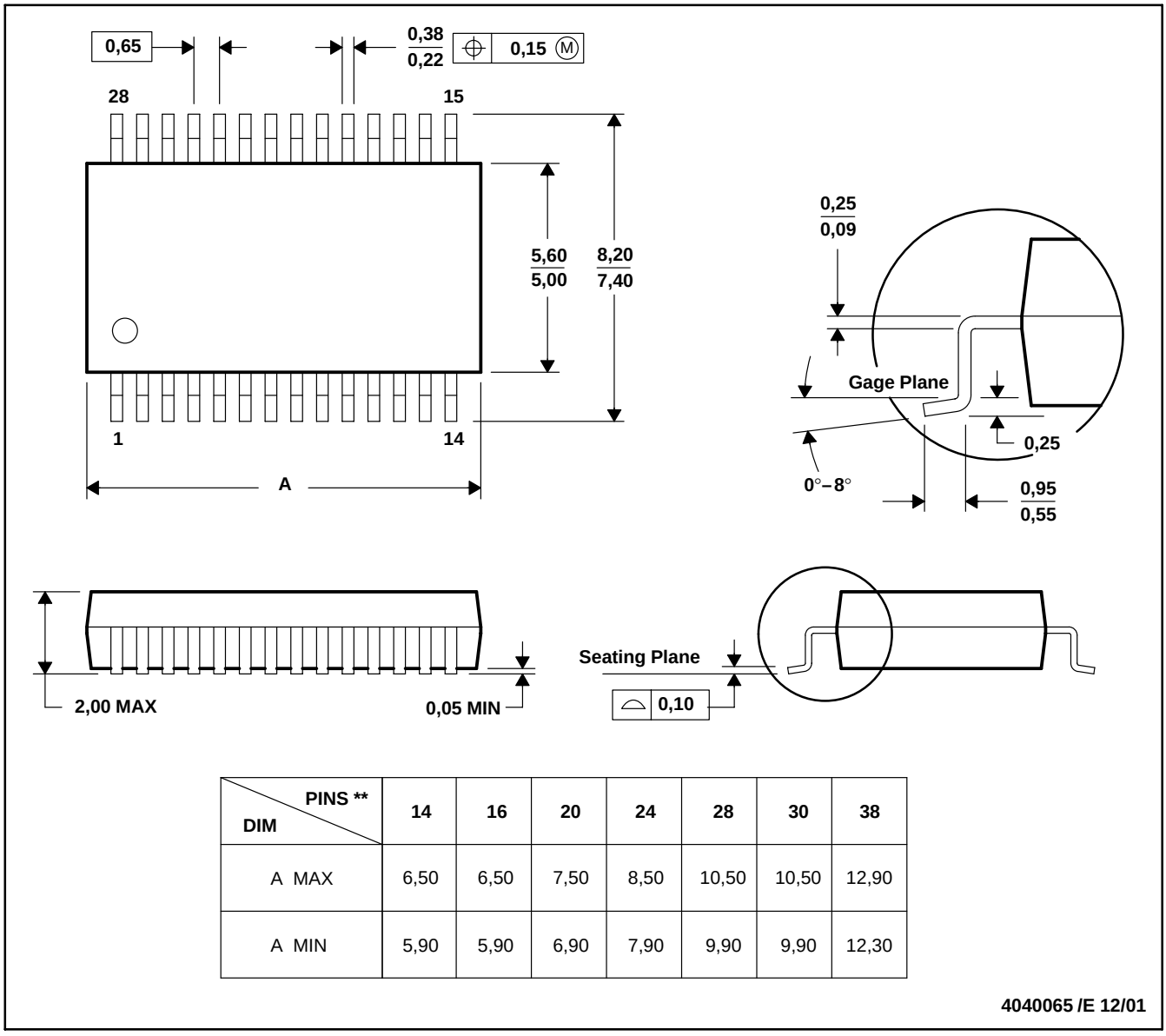
NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

MSSO002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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